SAMSUNG

GSM TELEPHONE

SGH-C266

SERVICE Manual

GSM TELEPHONE

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SAMSUNG ELECTRONICS

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1. Safety Precautions

1-1. Repair Precaution

- Repair in Shield Box, during detailed tuning. Take specially care of tuning or test, because specipicty of cellular phone is sensitive for surrounding interference(RF noise).

- Be careful to use a kind of magnetic object or tool, because performance of parts is damaged by the influence of manetic force.

- Surely use a standard screwdriver when you disassemble this product, otherwise screw will be worn away.

- Use a thicken twisted wire when you measure level. A thicken twisted wire has low resistance, therefore error of measurement is few.

- Repair after separate Test Pack and Set because for short danger (for example an overcurrent and furious flames of parts etc) when you repair board in condition of connecting Test Pack and tuning on.

- Take specially care of soldering, because Land of PCB is small and weak in heat.

- Surely tune on/off while using AC power plug, because a repair of battery charger is dangerous when tuning ON/OFF PBA and Connector after disassembing charger.

- Don't use as you pleases after change other material than replacement registered on SEC System. Otherwise engineer in charge isn't charged with problem that you don't keep this rules.

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1-2. ESD(Electrostatically Sensitive Devices) Precaution

Several semiconductor may be damaged easilly by static electricity. Such parts are called by ESD(Electrostatically Sensitive Devices), for example IC,BGA chip etc. Read Precaution below. You can prevent from ESD damage by static electricity.

- Remove static electricity remained your body before you touch semiconductor or parts with semiconductor. There are ways that you touch an earthed place or wear static electricity prevention string on wrist.

- Use earthed soldering steel when you connect or disconnect ESD.

- Use soldering removing tool to break static electricity. , otherwise ESD will be damaged by static electricity.

- Don't unpack until you set up ESD on product. Because most of ESD are packed by box and aluminum plate to have conductive power,they are prevented from static electricity.

- You must maintain electric contact between ESD and place due to be set up until ESD is connected completely to the proper place or a circuit board.

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2. Specification

2-1. GSM General Specification

	GSM 850 Phase 2	DCS1800 Phase 1	PCS1900
Freq. Band[MHz] Uplink/Downlink	824.2~848.8 869.2~893.8	1710~1785 1805~1880	1850~1910 1930~1990
ARFCN range	128~251	512~885	512~810
Tx/Rx spacing	45 MHz	95 MHz	80 MHz
Mod. Bit rate/ Bit Period	270.833 kbps 3.692 us	270.833 kbps 3.692 us	270.833 kbps 3.692 us
Time Slot Period/Frame Period	576.9 us 4.615 ms	576.9 us 4.615 ms	576.9 us 4.615 ms
Modulation	0.3 GMSK	0.3 GMSK	0.3 GMSK
MS Power	33 dBm~5 dBm	30 dBm~0 dBm	30 dBm~0 dBm
Power Class	5 pcl ~ 19 pcl	0 pcl ~ 15 pcl	0 pcl ~ 15 pcl
Sensitivity	-102 dBm	-100 dBm	-100 dBm
TDMA Mux	8	8	8
Cell Radius	35 Km	2 Km	-

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2-2. GSM Tx Power Class

TX Power control level	GSM850
5	33±2 dBm
6	31±2 dBm
7	29±2 dBm
8	27±2 dBm
9	25±2 dBm
10	23±2 dBm
11	21±2 dBm
12	19±2 dBm
13	17±2 dBm
14	15±2 dBm
15	13±2 dBm
16	11±3 dBm
17	9±3 dBm
18	7±3 dBm
19	5±3 dBm

TX Power control level	DCS1800
0	30±3 dBm
1	28±3 dBm
2	26±3 dBm
3	24±3 dBm
4	22±3 dBm
5	20±3 dBm
6	18±3 dBm
7	16±3 dBm
8	14±3 dBm
9	12±4 dBm
10	10±4 dBm
11	8±4 dBm
12	6±4 dBm
13	4±4 dBm
14	2±5 dBm
15	0±5 dBm

TX Power control level	PCS1900
0	30±3 dBm
1	28±3 dBm
2	26±3 dBm
3	24±3 dBm
4	22±3 dBm
5	20±3 dBm
6	18±3 dBm
7	16±3 dBm
8	14±3 dBm
9	12±4 dBm
10	10±4 dBm
11	8±4 dBm
12	6±4 dBm
13	4±4 dBm
14	2±5 dBm
15	0±5 dBm

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3. Product Function

Main Function

-Web browser

Access the wireless web to get current information and up-to-the-minute a wide variety of media content.

-Java

Enjoy Java™-based embedded games and download new games.

-Multimedia Message Service(MMS)

Send and receive MMS messages with a combination of text, image, video, and audio.

-E-mail

Send and receive-emails with image, video,and audio attachments.

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4. Array course control

4-1. Software Adjustments

Test Jig (GH80-00865A)

Test Cable (GH39-00127A)

RF Test Cable (GH39-00397A)

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4-2. Software Downloading

4-2-1. Downloading Binary Files

- Three binary files for downloading C266.
  – C266XXYY.s3 : Main source code binary.

4-2-2. Pre-requsite for Downloading

- Downloader Program(OptiFlash.exe)
- C266 Mobile Phone
- Data Cable
- Binary files

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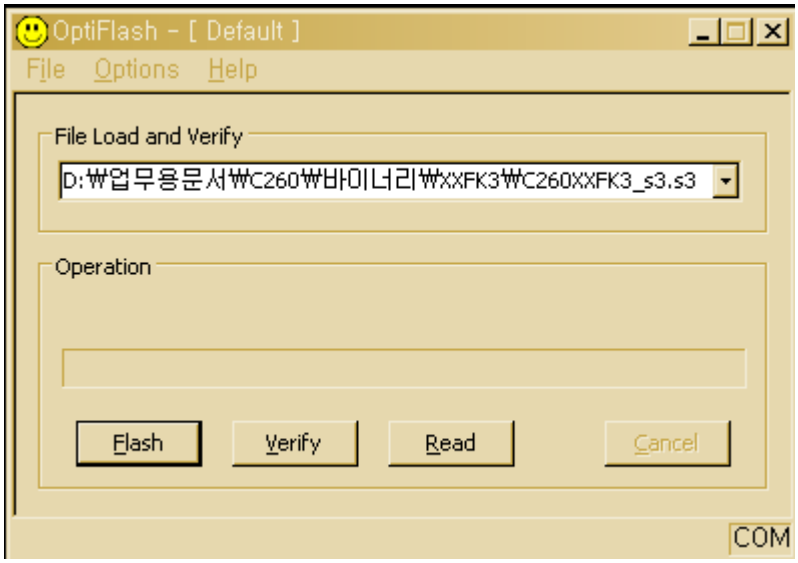
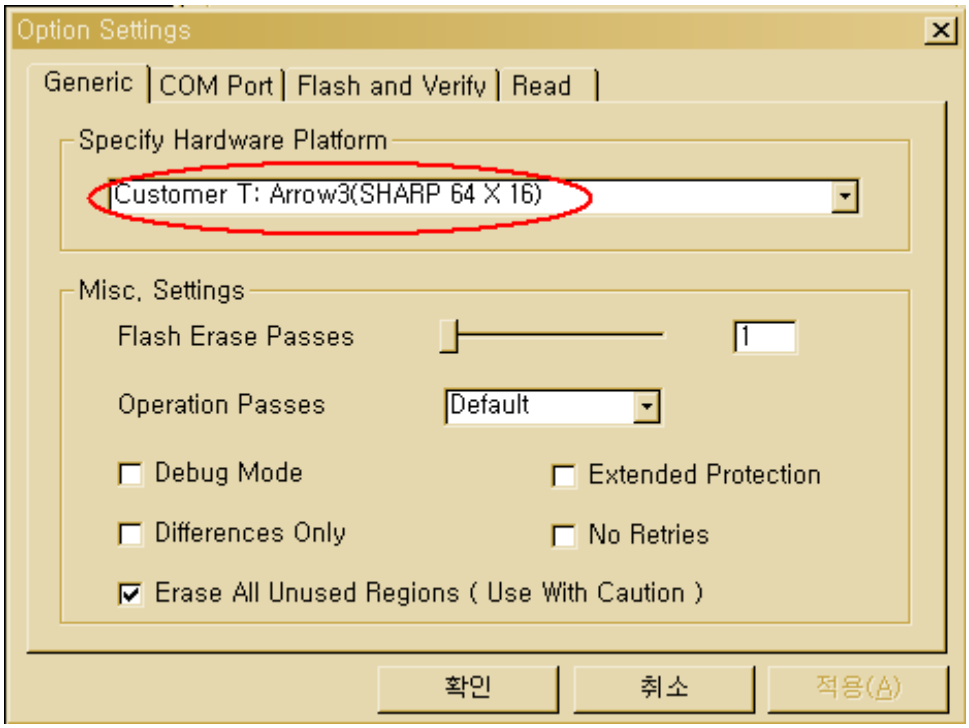
4-2-3. S/W Downloader Program

1. Load the binary download program by executing the "**OptiFlash.exe**"



2. Select the **"Options" -> "Settings" -> "Generic" -> "Specify hardware platform**". Choose hardware platform for the downloader file setting.
Set the everything else as the default values which are shown below



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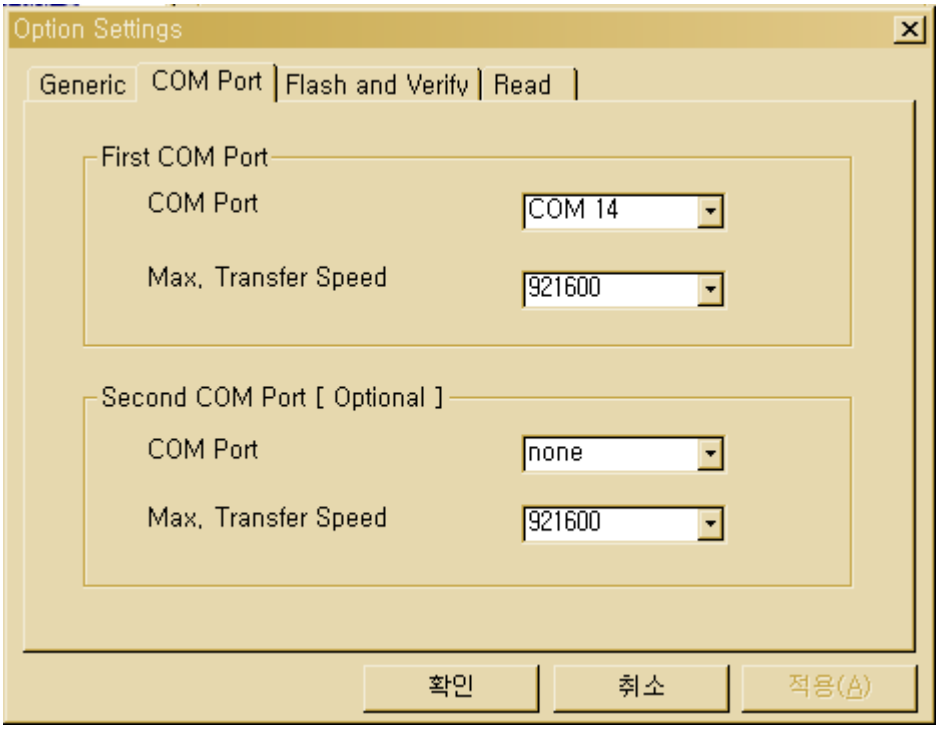
3. Select the **COM port** when the download cable is connected



Up to twelve ports are supported. Additionally you can select the maximum transfer speed OptiFlash will use to communicate with the phone. However, OptiFlash will use a slower speed if either the PC's or the phone's serial hardware is incapable of handling the selected speed

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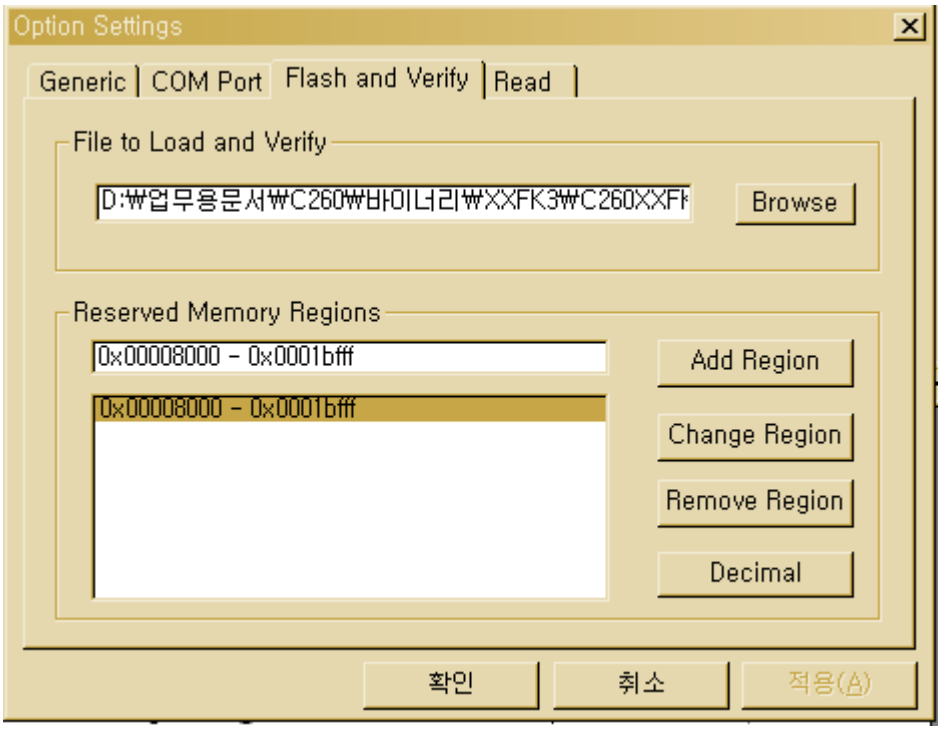
4. Select the“**Flash&Verify” -> “Browse**”

Set the directory path and choose the latest s/w binary, for example “C266XXYY.s3”, for the downloader binary setting.



Make sure that not to change the reserved memory regions.

In case of C140 the reserved memory regions are :

-0x00008000 – 0x0001bfff

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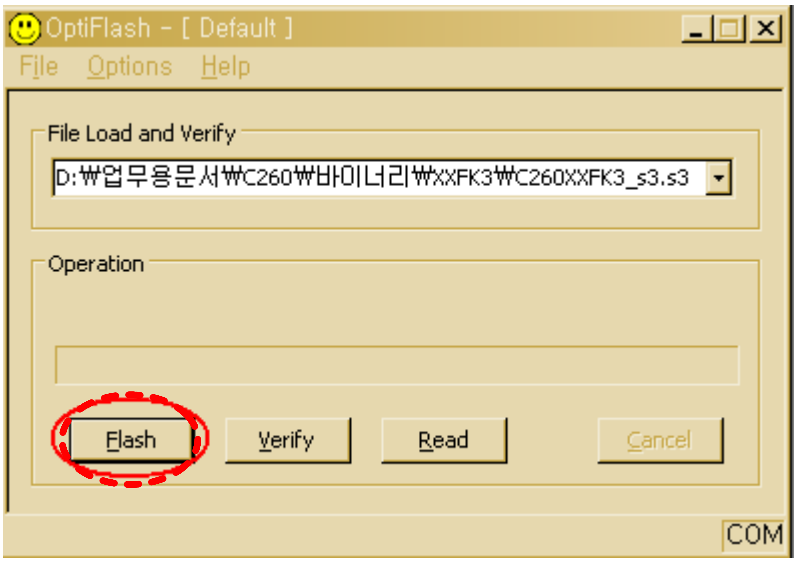
5. Click “**OK**” button then press “**Flash**”.
(Before pressing ‘Flash’ button, push the button **‘*’and ‘END’ at the same time**. Then press ‘Flash’.)

Downloader will upload the binary file as below for the downloading.



6. When downloading is finished successfully, there is a “All is well” message.

7. After finishing downloading, Certain memory resets should be done to guarantee the normal performance.

8. Confirm the downloaded version name and etc. :

***#1111#**

Full Reset :

***2767*3855#**

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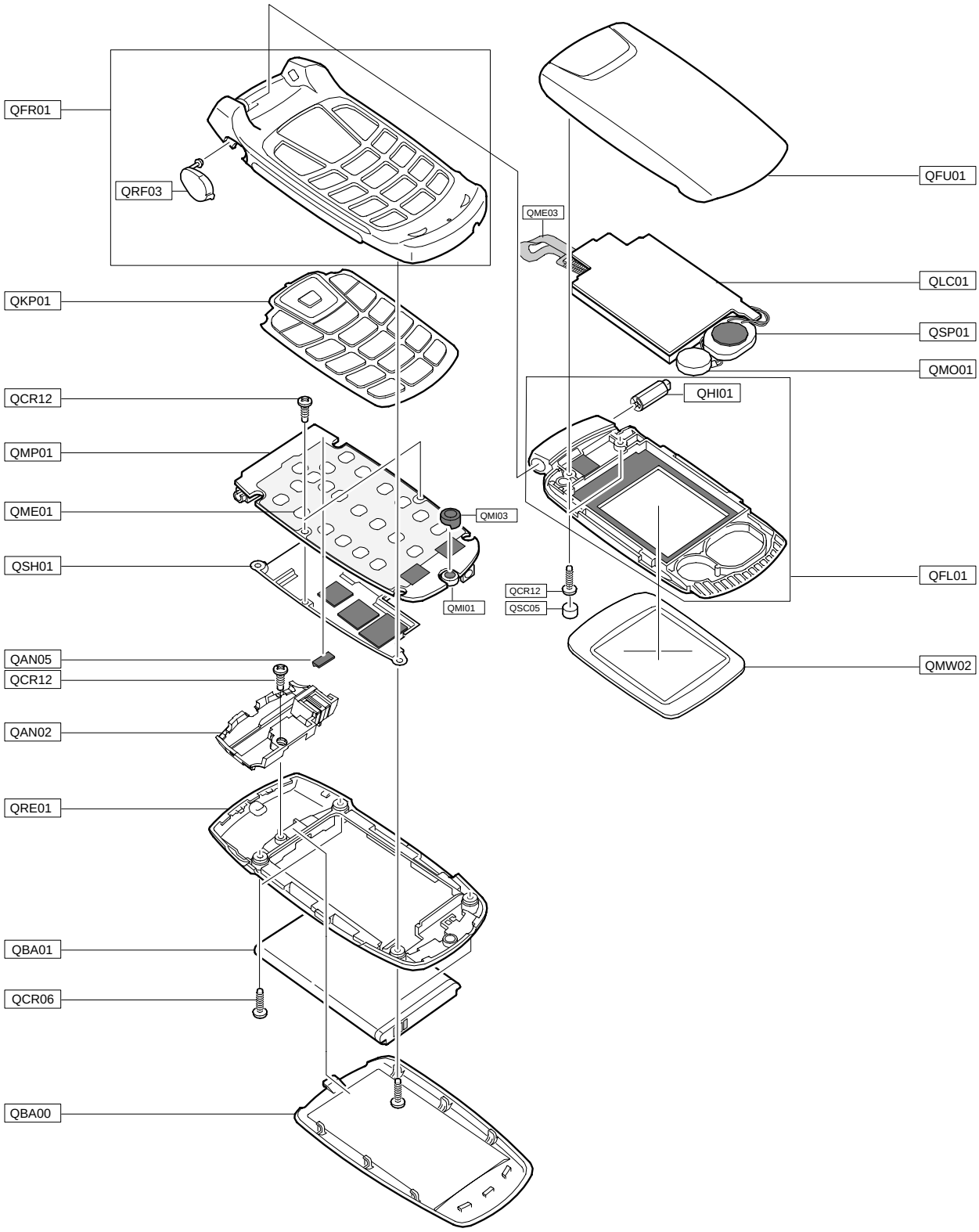
5. Exploded View/Disassembly&Assembly Instructions

5-1. Cellular phone Exploded View



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5-2. Cellular phone Parts list

Design LOC	Description	SEC CODE
QAN02	INTENNA-SGHC266	GH42-01118A
QAN05	ASSY MEC-INTENNA CONTACT	GH75-08168A
QBA00	PMO-CASE BATTERY	GH72-36766A
QBA01	INNER BATTERY PACK-750MAH BLK	GH43-02489A
QCR06	SCREW-MACHINE	6001-001155
QCR12	SCREW-MACHINE	6001-001530
QCR12	SCREW-MACHINE	6001-001530
QCR12	SCREW-MACHINE	6001-001530
QFL01	ASSY CASE-LOWER	GH98-03404A
QFR01	ASSY CASE-FRONT	GH98-03403A
QFU01	ASSY CASE-UPPER	GH98-03405B
QHI01	ASSY MEC-HINGE	GH75-08452A
QKP01	ASSY KEYPAD-(XEN/WS)	GH98-03772B
QLC01	LCD-MODULE SGH-C260	GH07-01138A
QME01	UNIT-SGHC260 METAL DOME(MAIN)	GH59-04084A
QME03	UNIT-SGHC260 CON TO CON	GH59-04070A
QMI01	MICROPHONE-ASSY-6.25MM	GH30-00177F
QMI03	RMO-MIC HOLDER	GH73-05342A
QMO01	MOTOR DC-SGHC260	GH31-00308A
QMP01	A/S ASSY-PBA MAIN	GH82-02224A
QMW02	PMO-COVER MAIN WINDOW	GH72-36767A
QRE01	ASSY CASE-REAR	GH98-03406A
QRF03	PMO-CASE EAR	GH72-36761A
QSC05	RMO-COVER FOLDER SCREW	GH73-09088A
QSH01	ASSY CASE-SHIELD CAN	GH98-03407A
QSP01	SPEAKER	3001-002094

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Description	SEC CODE
LABEL(R)-WATER SOAK	GH68-09361A
MPR-TAPE DOPARO LED	GH74-30219A
RMO-COVER DUMMY HOLE	GH73-08828A
MPR-VINYL BOHO LCD WIN	GH74-20912A
MPR-VINYL BOHO WINDOW JIG	GH74-30221A
MPR-TAPE MAIN WINDOW	GH74-29604A
MPR-SPONGE	GH74-31189A
MPR-INSU TAPE	GH74-30658A
MPR-SPONGE	GH74-30223A
MANUAL USERS-LTN ENGLISH	GH68-13795A
MANUAL USERS-LTN SPANISH	GH68-13796A
BAG PE	6902-000634
LABEL(P)-MIAMI	GH68-12219A
LABEL(R)-MAIN(LTN)	GH68-13763B
BOX-UNIT(LTN_MOVISTAR)	GH69-05011D
ADAPTOR-SGHC266, MEXC ,BLK	GH44-01632A

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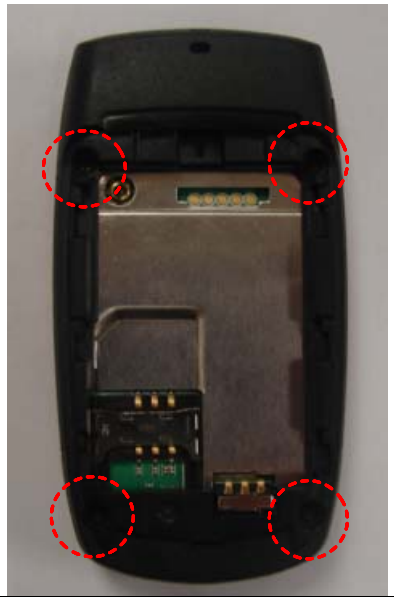
5-3. Disassembly and Assembly Instructions

5-3-1. Disassembly

1

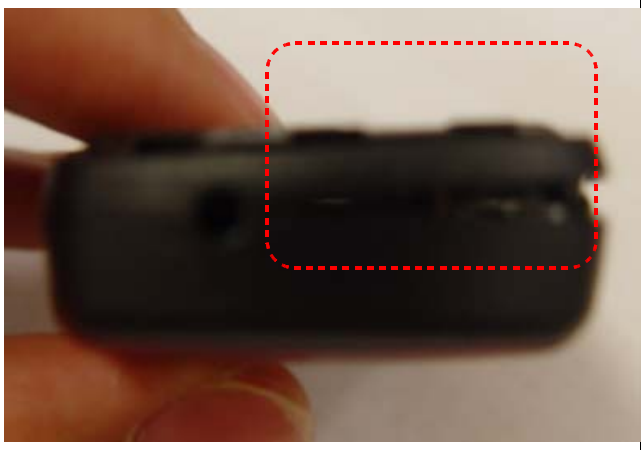


1) Unscrew the REAR.(4 points)
※ **caution**
1) Be careful not to make scratch and molding d amage!

2

1) Lift up the lockers in the center of set.
※ **caution**
1) Be careful not to make scratch and molding damage!
2) Remove the lockers in the center by all means.

3



1) Lift up the lockers in the bottom of set.
※ **caution**
1) Be careful not to make scratch and molding damage!

4

1) Twist the REAR off the set carefully.
※ **caution**
1) Be careful not to make scratch and molding damage!

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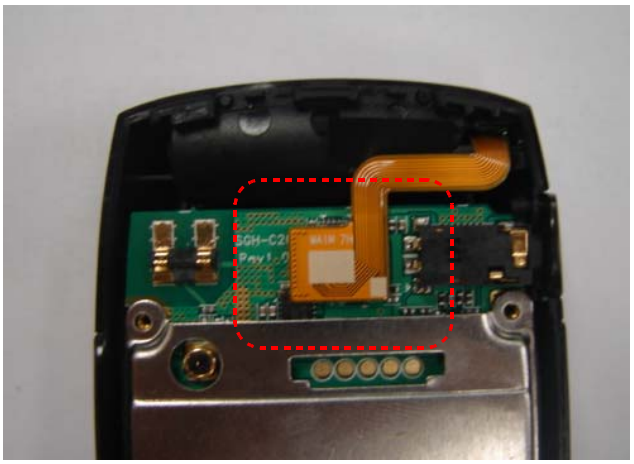
5



1) Remove the CON TO CON.

※ **caution**

1) Be careful not to make scratch and molding damage!

2) Be careful not to damage the CON TO CON .

6

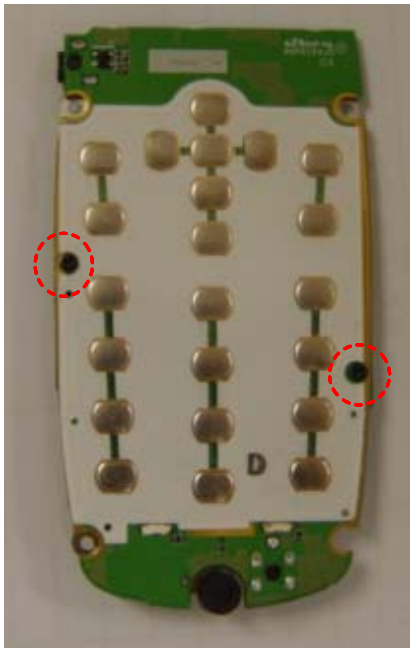
1) Remove the PBA placed at the FRONT.

※ **caution**

1) Be careful not to make scratch and molding damage!

2) Be careful not to damage the CON TO CON .

7



1) Unscrew the SHIELD-CAN.(2 points)

※ **caution**

1) Be careful not to make scratch and molding damage!

8

1) Remove the KEY-PAD placed at the Front.

※ **caution**

1) Be careful not to make scratch and molding damage!

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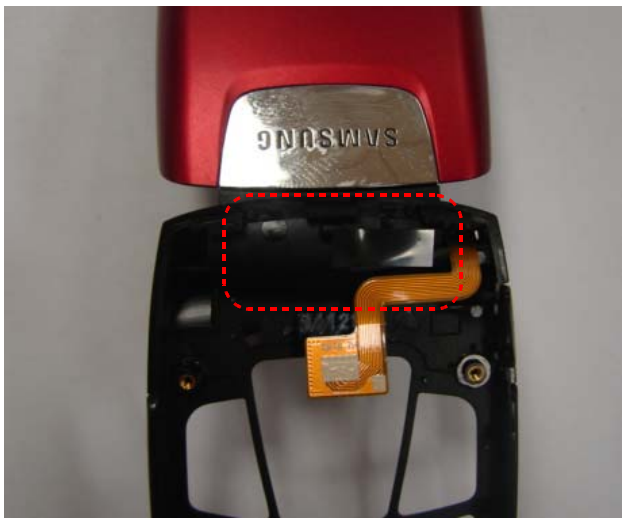
9



1) Remove the tape.

※ **caution**

1) Be careful not to make scratch and molding damage!
2) Be careful not to damage the CON TO CON .

10

1)Seperate the FRONT from the FOLDER assembled.

※ **caution**

1) Be careful not to make scratch and molding damage!
2) Be careful not to damage the CON TO CON .

11

1) Remove the screw caps and unscrew the LOWER. (2points)

※ **caution**

1) Be careful not to make scratch and molding damage!

12

1) Lift up the bottom of LOWER removing the lockers with a tool.

※ **caution**

1) Be careful not to make scratch and molding damage!

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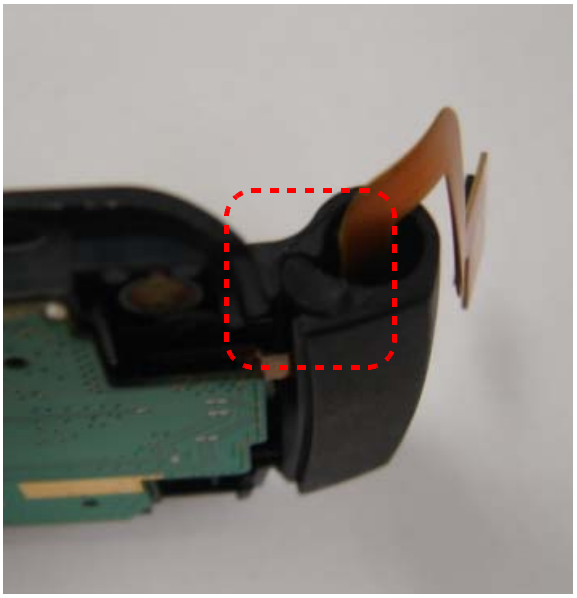
13

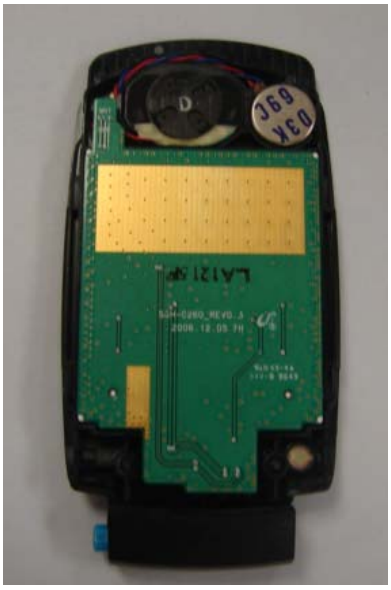


1) Take the rubber out.

※ **caution**

1) Be careful not to make scratch and molding damage!

14



1) Remove the LCD F-PCB.

※ **caution**

1) Be careful not to make scratch and molding damage!

15

1) Remove the LCD carefully so that the nonwoven on speaker and motor is not damaged.

※ **caution**

1) Be careful not to make scratch and molding damage!

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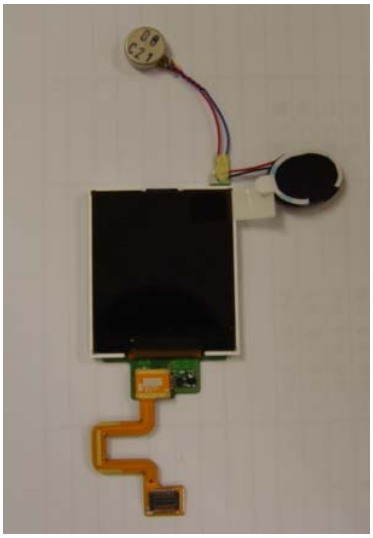
5-3-2. Assembly

1



1)Put the CON TO CON on the LCD Module it clicks.

※ **caution**

1) Be careful not to make scratch and molding damage!

2) Be careful not to damage the LCD Module.

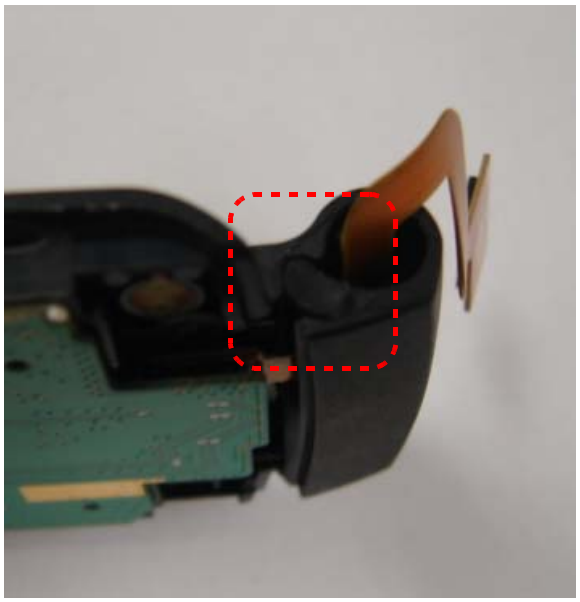
2

1) Put the LCD Module into place as shown .
2) Put the speaker and motor into place.

※ **caution**

1) Be careful not to make scratch and molding damage!

3



1) Place the MIC as the picture below

※ **caution**

1) Be careful not to make scratch and molding damage! TORQE (1.0 ± 0.1 Kgf·Cm)

4

1) Put the MIC COVER and CREW
2) Attach KEYPAD
3) Press the KEYPAD not to be detached

※ **caution**

1) Be careful not to make scratch and molding damage!

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5

1) Fasten 2 screws.
2) Put the screw caps on the FOLDER.

※ **caution**

1) Be careful not to make scratch and molding damage!

TORQE (1.0 ± 0.1 Kgf·Cm)

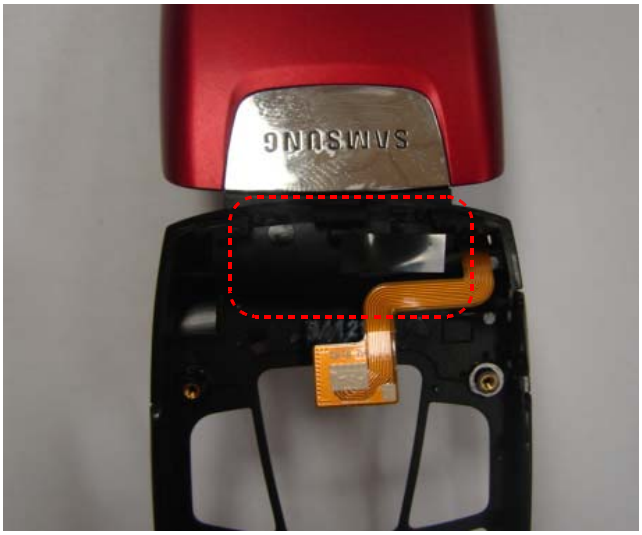
6

1) Put one side of the FOLDER into the FRONT firstly,do the other side pressing the hinge.

※ **caution**

1)Be careful not to damage the F-PCB.

7



1) Put a tape on.

※ **caution**

1) Be careful not to damage the wire on the speaker due to PBA.

8

1) Place the KEY-PAD into the FRONT.

※ **caution**

1) Be careful not to make scratch and molding damage!

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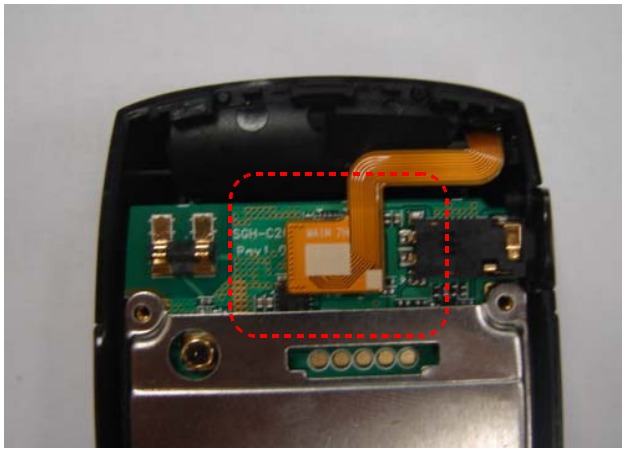

1) As shown,put the CON TO CON on PBA.

※ **caution**

1) Be careful not to make scratch and molding damage!
2) Press the CON TO CON down firmly.

10

1) Press the bottom of REAR down until it clicks.

※ **caution**

1) Be careful not to make scratch and molding damage!
2) Be careful not to damage the locker.

11

1) Press the both sides of the REAR using the lockers.

※ **caution**

1) Be careful not to make scratch and molding damage!
2) Be careful not to damage the locker.

12

1) Press the top down until the lockers click grasping with your fingers carefully.

※ **caution**

1) Be careful not to make scratch and molding damage!
2) Be careful not to damage the locker.

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6. MAIN Electrical Parts List

Design LOC	Description	SEC Code	STATUS
ANT	NPR-ANTENNA CONTACT	GH71-04813A	SA
BTC301	HEADER-BATTERY	3711-006228	SA
C100	C-CER,CHIP	2203-006423	SA
C101	C-CER,CHIP	2203-006194	SA
C102	C-CER,CHIP	2203-002668	SA
C103	C-CER,CHIP	2203-005736	SA
C105	C-CER,CHIP	2203-005682	SA
C106	C-CER,CHIP	2203-005742	SA
C107	C-CER,CHIP	2203-005742	SA
C108	C-CER,CHIP	2203-005683	SA
C109	C-CER,CHIP	2203-005683	SA
C110	C-CER,CHIP	2203-005736	SA
C111	C-CER,CHIP	2203-006318	SA
C112	C-CER,CHIP	2203-006423	SA
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C114	C-CER,CHIP	2203-005682	SA
C115	C-CER,CHIP	2203-005682	SA
C116	C-CER,CHIP	2203-005682	SA
C117	C-CER,CHIP	2203-005736	SA
C119	C-CER,CHIP	2203-006556	SA
C120	C-CER,CHIP	2203-000812	SA
C121	C-CER,CHIP	2203-006260	SA
C122	C-CER,CHIP	2203-006187	SA
C123	C-CER,CHIP	2203-006047	SA
C124	C-CER,CHIP	2203-006423	SA
C125	C-CER,CHIP	2203-006187	SA
C126	INDUCTOR-SMD	2703-002205	SA
C127	C-CER,CHIP	2203-000386	SA
C129	C-CER,CHIP	2203-001412	SA
C130	C-CER,CHIP	2203-005736	SA
C132	C-CER,CHIP	2203-005719	SA
C133	C-CER,CHIP	2203-006048	SA
C134	C-CER,CHIP	2203-000627	SNA
C138	C-CER,CHIP	2203-000940	SA
C139	C-CER,CHIP	2203-005482	SA
C140	C-CER,CHIP	2203-000995	SA
C141	C-CER,CHIP	2203-000995	SA
C142	C-CER,CHIP	2203-000995	SA
C145	C-CER,CHIP	2203-005719	SA
C146	C-CER,CHIP	2203-006194	SA
C147	C-CER,CHIP	2203-000254	SA
C150	C-CER,CHIP	2203-005482	SA
C151	C-CER,CHIP	2203-006626	SA
C152	C-CER,CHIP	2203-000254	SA
C153	C-CER,CHIP	2203-000254	SA
C155	C-CER,CHIP	2203-005482	SA
C162	C-CER,CHIP	2203-006324	SA
C163	C-CER,CHIP	2203-006708	SA
C164	C-CER,CHIP	2203-005482	SA
C165	C-CER,CHIP	2203-000254	SA

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Design LOC	Description	SEC Code	STATUS
C166	C-CER,CHIP	2203-000654	SA
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C168	C-CER,CHIP	2203-005065	SA
C169	C-CER,CHIP	2203-000714	SA
C170	C-CER,CHIP	2203-005065	SA
C171	C-CER,CHIP	2203-005065	SA
C172	C-CER,CHIP	2203-006708	SA
C173	C-CER,CHIP	2203-005065	SA
C174	C-CER,CHIP	2203-006708	SA
C175	C-CER,CHIP	2203-000233	SA
C176	C-CER,CHIP	2203-000438	SA
C177	C-CER,CHIP	2203-006708	SA
C178	C-CER,CHIP	2203-005482	SA
C179	C-CER,CHIP	2203-006137	SA
C180	C-CER,CHIP	2203-005482	SA
C182	C-CER,CHIP	2203-006562	SA
C183	C-CER,CHIP	2203-006423	SA
C184	C-CER,CHIP	2203-000854	SA
C185	C-CER,CHIP	2203-000438	SA
C186	C-CER,CHIP	2203-006361	SA
C188	C-CER,CHIP	2203-005249	SA
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C199	C-CER,CHIP	2203-000995	SA
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C210	C-CER,CHIP	2203-006260	SA
C211	C-CER,CHIP	2203-000254	SA
C212	C-CER,CHIP	2203-005482	SA
C213	C-CER,CHIP	2203-000254	SA
C214	C-CER,CHIP	2203-005482	SA
C215	C-CER,CHIP	2203-000254	SA
C216	C-CER,CHIP	2203-006260	SA
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C225	C-CER,CHIP	2203-000995	SA
C226	C-CER,CHIP	2203-006626	SA

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Design LOC	Description	SEC Code	STATUS
C227	C-CER,CHIP	2203-006562	SA
C228	C-CER,CHIP	2203-006562	SA
C229	C-CER,CHIP	2203-006562	SA
C230	C-CER,CHIP	2203-006626	SA
C301	C-CER,CHIP	2203-005482	SA
C304	C-CER,CHIP	2203-006626	SA
C305	C-CER,CHIP	2203-000995	SA
C306	C-CER,CHIP	2203-000233	SA
C307	C-CER,CHIP	2203-000995	SA
C308	C-CER,CHIP	2203-006137	SA
C309	C-CER,CHIP	2203-000233	SA
C310	C-CER,CHIP	2203-006626	SA
C311	C-CER,CHIP	2203-000812	SA
C313	C-CER,CHIP	2203-006257	SA
C314	C-CER,CHIP	2203-006824	SA
C316	C-CER,CHIP	2203-005482	SA
C319	C-CER,CHIP	2203-000278	SA
C321	C-CER,CHIP	2203-001072	SA
C322	C-CER,CHIP	2203-005482	SA
C326	C-CER,CHIP	2203-000386	SA
C327	C-CER,CHIP	2203-000386	SA
C330	C-CER,CHIP	2203-000854	SA
C331	C-CER,CHIP	2203-000854	SA
C335	C-CER,CHIP	2203-006361	SA
C338	C-CER,CHIP	2203-000386	SA
C339	C-CER,CHIP	2203-006978	SA
DCJ301	JACK-DC POWER	3722-002433	SA
EAR300	JACK-EAR PHONE	3722-002067	SA
F101	FILTER-SAW	2904-001633	SA
F102	FILTER-SAW	2904-001599	SA
F103	FILTER-SAW	2904-001600	SA
F104	BEAD-SMD	3301-001342	SA
F200	FILTER-EMI SMD	2901-001296	SA
F201	FILTER-EMI SMD	2901-001296	SA
F202	FILTER-EMI SMD	2901-001296	SA
GND	NPR-ANTENNA CONTACT	GH71-04813A	SA
HDC200	HEADER-BOARD TO BOARD	3711-005954	SA
L101	INDUCTOR-SMD	2703-002313	SA
L102	C-CER,CHIP	2203-000233	SA
L103	INDUCTOR-SMD	2703-002917	SA
L104	INDUCTOR-SMD	2703-002917	SA
L106	INDUCTOR-SMD	2703-001733	SA
L110	INDUCTOR-SMD	2703-002558	SA
L112	INDUCTOR-SMD	2703-001236	SA
L114	INDUCTOR-SMD	2703-001990	SA
L200	BEAD-SMD	3301-001342	SA
L406	INDUCTOR-SMD	2703-001733	SA
LED301	LED	0601-002160	SA
LED302	LED	0601-002160	SA
OSC101	CRYSTAL-SMD	2801-004587	SA

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Design LOC	Description	SEC Code	STATUS
OSC200	CRYSTAL-SMD	2801-003856	SA
PAM100	IC-POWER AMP	1201-002278	SA
R102	R-CHIP	2007-008043	SA
R117	R-CHIP	2007-000162	SA
R118	R-CHIP	2007-008516	SA
R131	R-CHIP	2007-002797	SA
R133	R-CHIP	2007-001308	SA
R143	R-CHIP	2007-000148	SA
R155	R-CHIP	2007-000164	SA
R156	R-CHIP	2007-000775	SA
R158	R-CHIP	2007-000775	SA
R159	R-CHIP	2007-001325	SA
R160	R-CHIP	2007-007861	SA
R170	R-CHIP	2007-008137	SA
R171	R-CHIP	2007-009160	SA
R172	R-CHIP	2007-000162	SA
R182	R-CHIP	2007-000162	SA
R183	R-CHIP	2007-001339	SA
R188	R-CHIP	2007-000157	SA
R189	R-CHIP	2007-000170	SA
R190	R-CHIP	2007-000170	SA
R195	R-CHIP	2007-008806	SA
R200	R-CHIP	2007-000172	SA
R201	R-CHIP	2007-000172	SA
R202	R-CHIP	2007-000157	SA
R203	R-CHIP	2007-000162	SA
R205	R-CHIP	2007-007573	SA
R207	R-CHIP	2007-007107	SA
R208	R-CHIP	2007-000162	SA
R209	R-CHIP	2007-007314	SA
R210	R-CHIP	2007-007573	SA
R211	R-CHIP	2007-000566	SA
R212	R-CHIP	2007-000566	SA
R213	R-CHIP	2007-000171	SA
R301	R-CHIP	2007-003112	SA
R302	R-CHIP	2007-003112	SA
R327	R-CHIP	2007-000566	SA
R335	R-CHIP	2007-000171	SA
R337	R-CHIP	2007-000171	SA
R339	R-CHIP	2007-000148	SA
R340	R-CHIP	2007-000242	SA
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R345	R-CHIP	2007-001323	SA
R347	R-CHIP	2007-001119	SA
R348	R-CHIP	2007-000831	SA
R349	R-CHIP	2007-000157	SA
R351	R-CHIP	2007-000171	SA

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R352	R-CHIP	2007-000171	SA
R353	R-CHIP	2007-001119	SA
R354	R-CHIP	2007-000242	SA
R355	R-CHIP	2007-000242	SA
R357	R-CHIP	2007-000173	SA
R358	R-CHIP	2007-000148	SA
R359	R-CHIP	2007-000161	SA
R360	R-CHIP	2007-001335	SA
R363	R-CHIP	2007-000148	SA
R364	R-CHIP	2007-000161	SA
R365	R-CHIP	2007-000173	SA
R366	R-CHIP	2007-000171	SA
R367	R-CHIP	2007-001288	SA
R368	R-CHIP	2007-001288	SA
R369	R-CHIP	2007-000140	SA
R370	R-CHIP	2007-000140	SA
R371	R-CHIP	2007-000140	SA
RFS100	CONNECTOR-COAXIAL	3705-001358	SA
SIM103	CONNECTOR-CARD EDGE	3709-001384	SA
TA100	C-TA,CHIP	2404-001374	SA
TA300	C-TA,CHIP	2404-001406	SA
TA301	C-TA,CHIP	2404-001393	SA
TA302	C-TA,CHIP	2404-001393	SA
TA303	C-TA,CHIP	2404-001352	SA
TH200	THERMISTOR-NTC	1404-001165	SA
TR100	TR-DIGITAL	0504-000168	SA
TR300	TR-SMALL SIGNAL	0501-000225	SA
U103	IC-CMOS LOGIC	0801-003013	SA
U105	IC-BATTERY	1203-003663	SA
U109	IC-CMOS LOGIC	0801-002529	SA
U201	IC-HALL EFFECT S/W	1009-001020	SA
U203	IC-DC/DC CONVERTER	1203-004051	SA
U300	IC-ANALOG SWITCH	1001-001371	SA
UCD101	IC-TRANSCEIVER	1205-003098	SA
UCD106	IC-MELODY	1204-001811	SA
UCD107	IC-POWER SUPERVISOR	1203-003897	SA
UCP200	IC MICOM	GH09-00041A	SA
UME200	IC-MCP	1108-000095	SA
VR300	VARISTOR	1405-001082	SA
VR301	VARISTOR	1405-001082	SA
VR302	VARISTOR	1405-001082	SA
VR303	VARISTOR	1405-001082	SA
VR304	VARISTOR	1405-001082	SA
VR307	VARISTOR	1405-001108	SA
VR309	VARISTOR	1405-001082	SA
VR310	VARISTOR	1405-001082	SA
VR311	VARISTOR	1405-001082	SA
VR312	VARISTOR	1405-001082	SA
VR313	VARISTOR	1405-001082	SA
VR314	VARISTOR	1405-001082	SA

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Design LOC	Description	SEC Code	STATUS
VR315	VARISTOR	1405-001082	SA
VR316	VARISTOR	1405-001082	SA
VR317	VARISTOR	1405-001082	SA
VR318	VARISTOR	1405-001082	SA
VR319	VARISTOR	1405-001082	SA
VR320	VARISTOR	1405-001082	SA
ZD300	DIODE-ZENER	0403-001547	SA
ZD301	DIODE-TVS	0406-001083	SA

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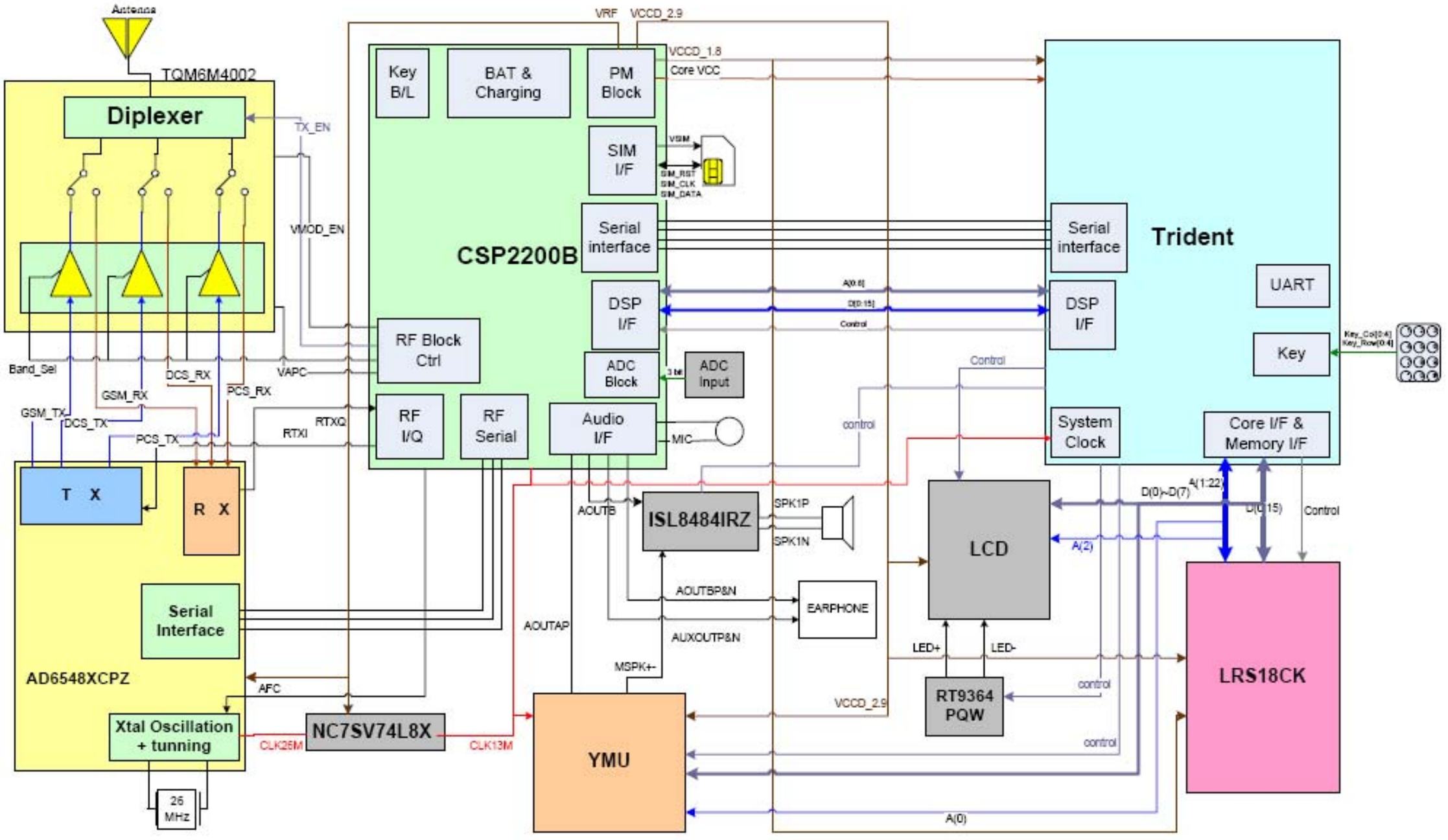
7. Block Diagrams



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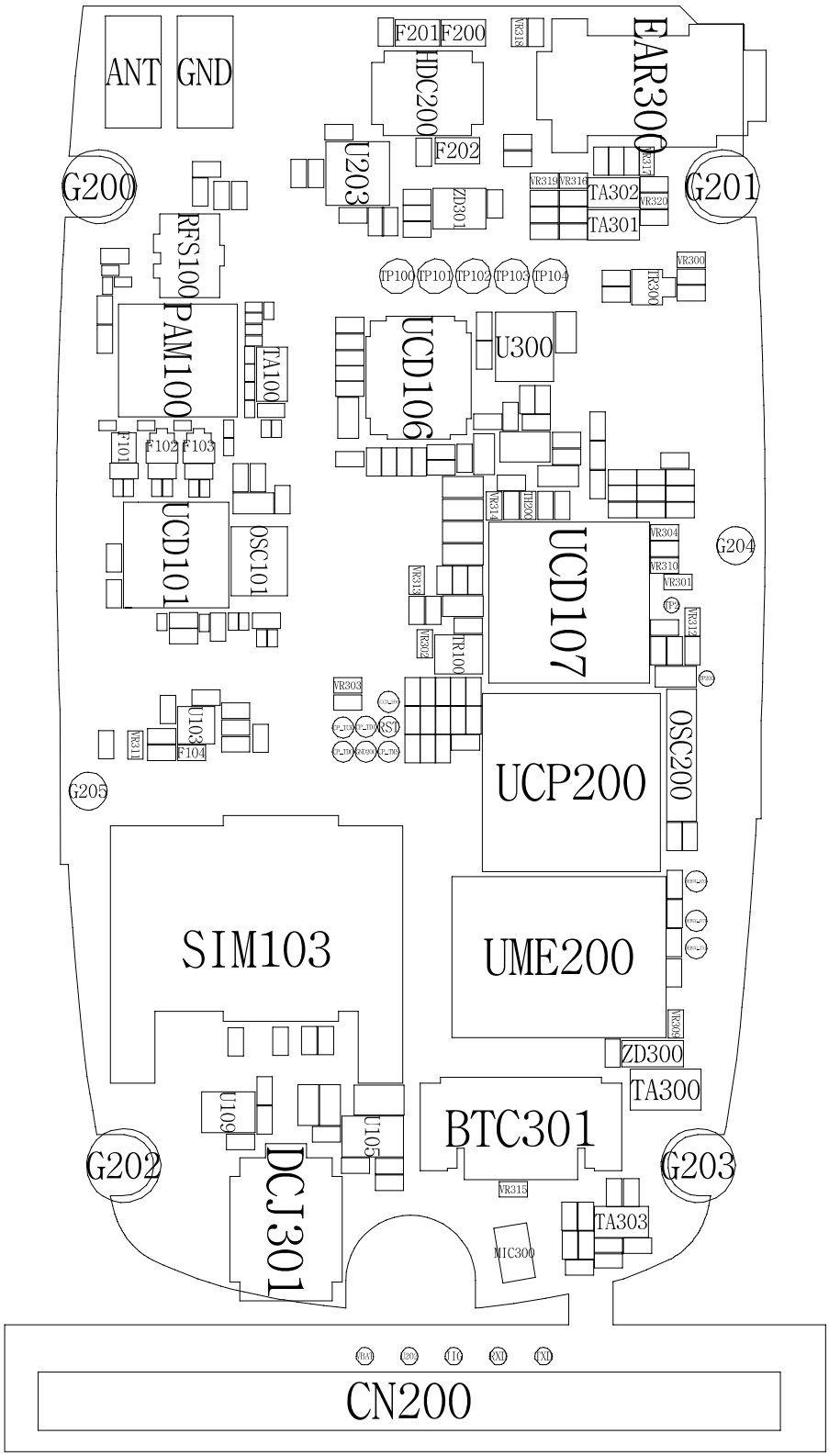
8. PCB Diagrams

Top



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Bottom

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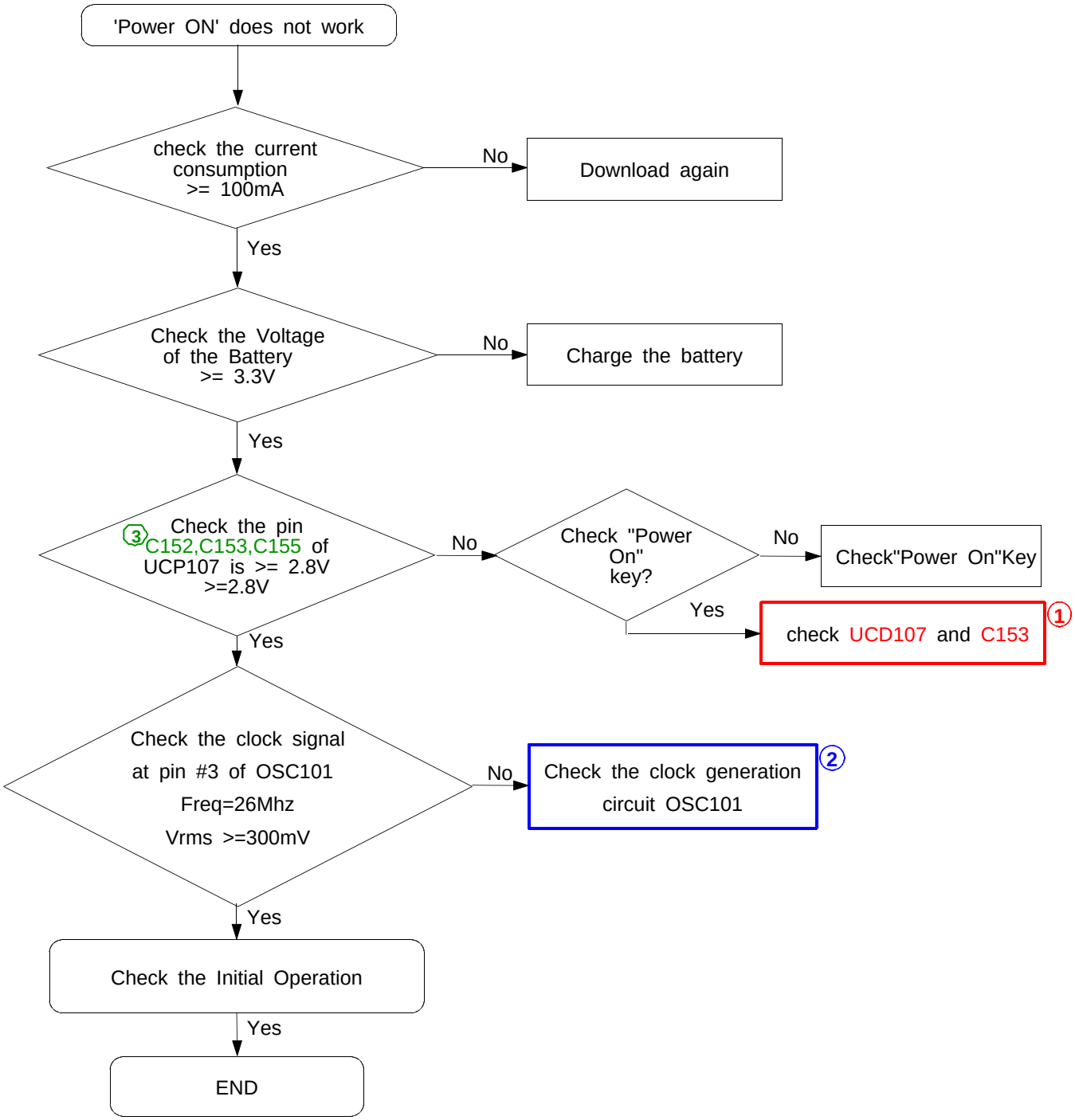
9. Flow Chart of Troubleshooting

9-1. Baseband

9-1-1. Power ON



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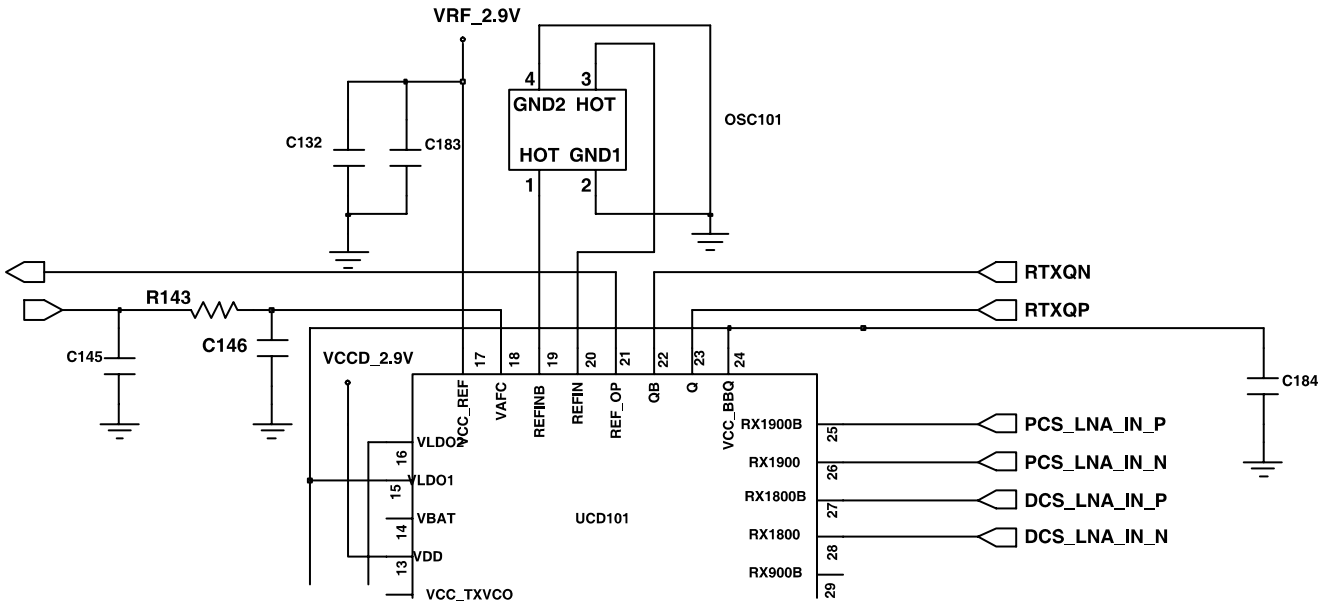

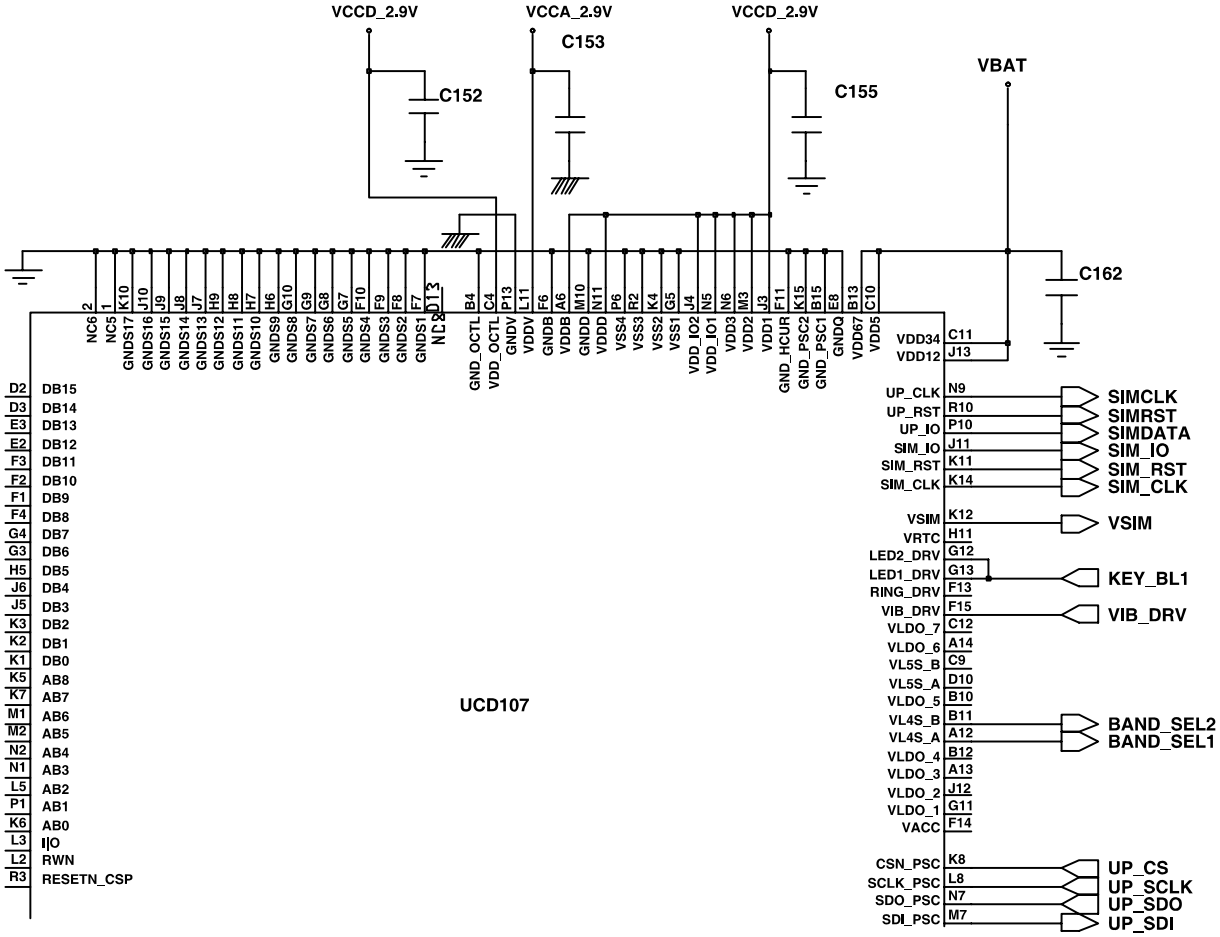

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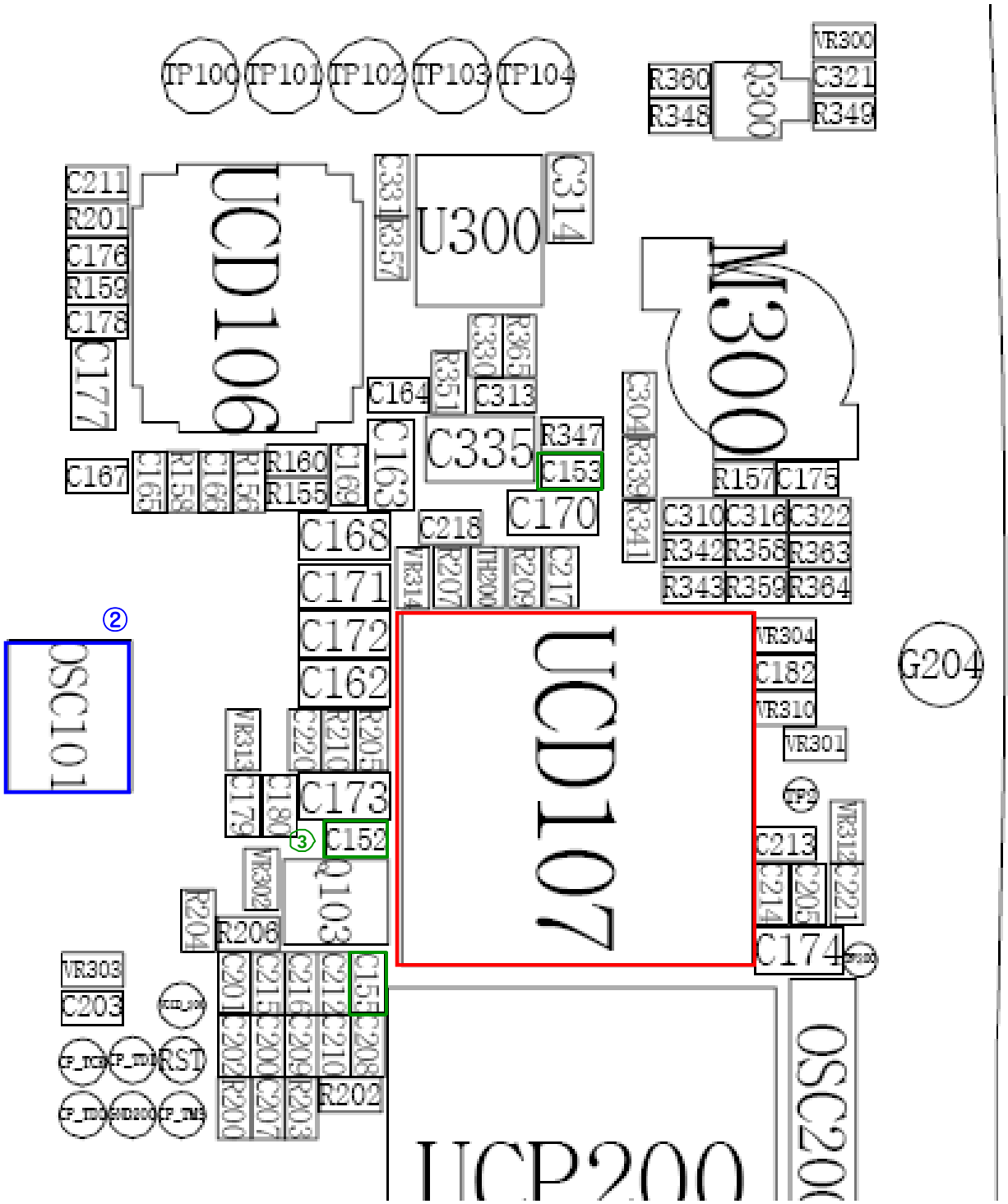

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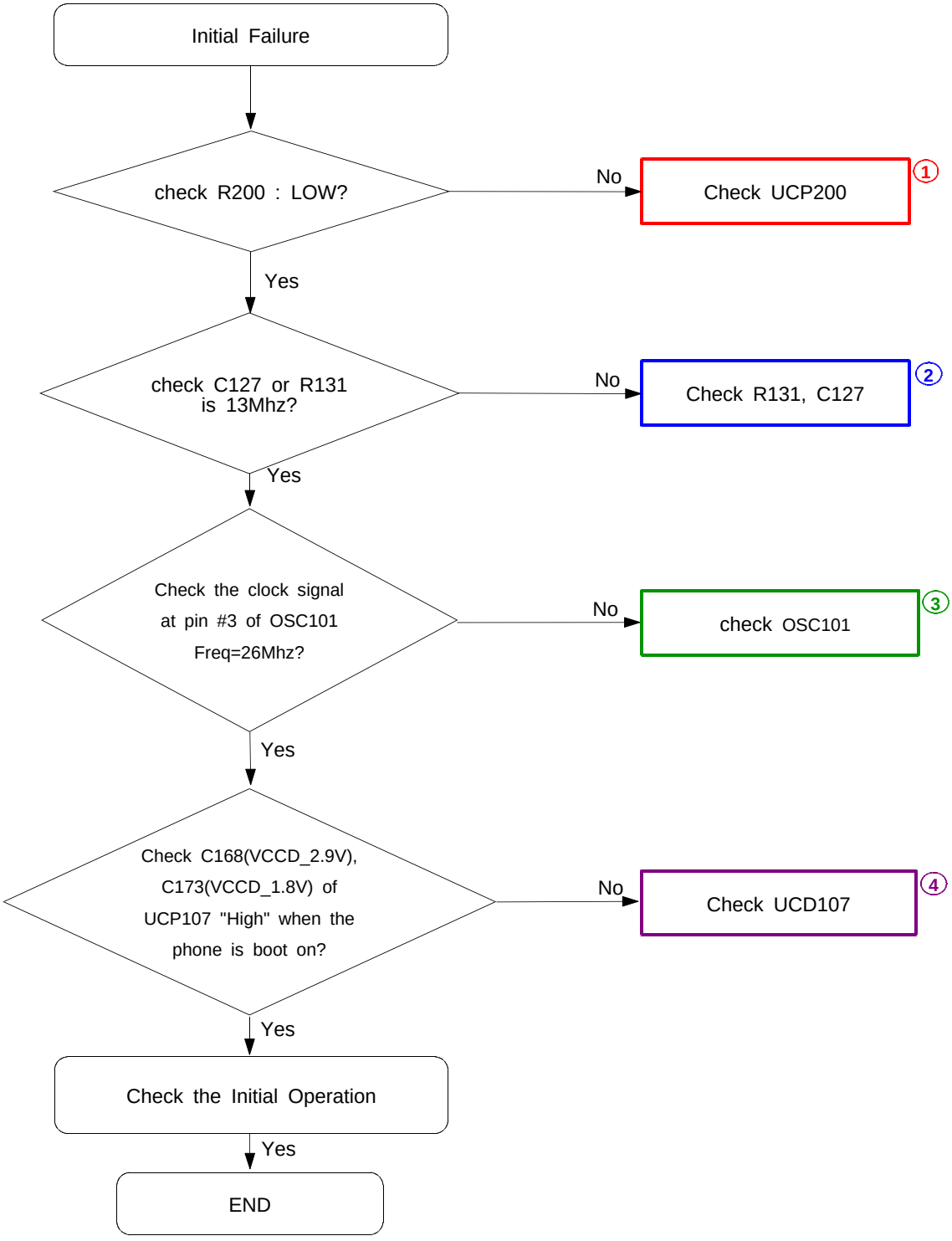
9-1-2. Initial



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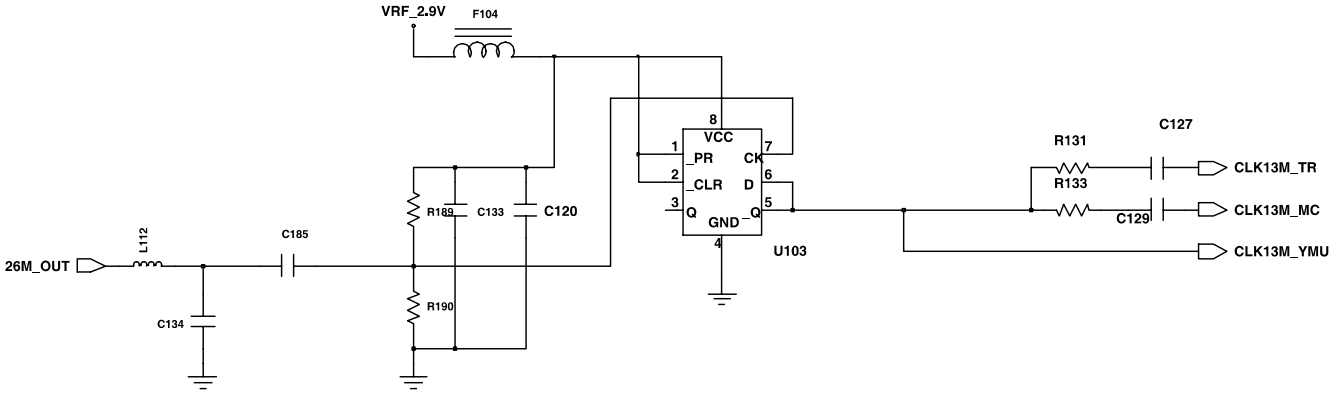

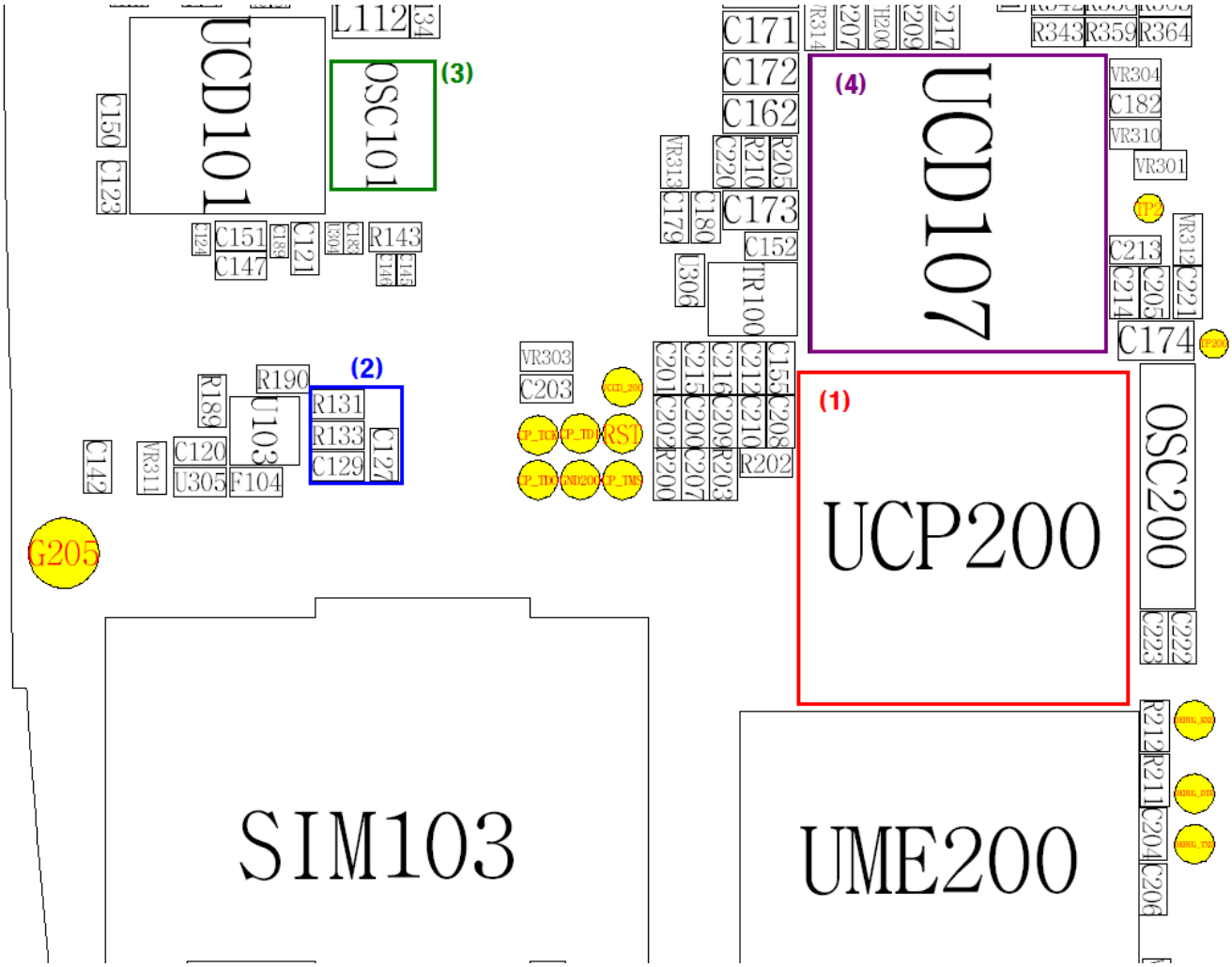

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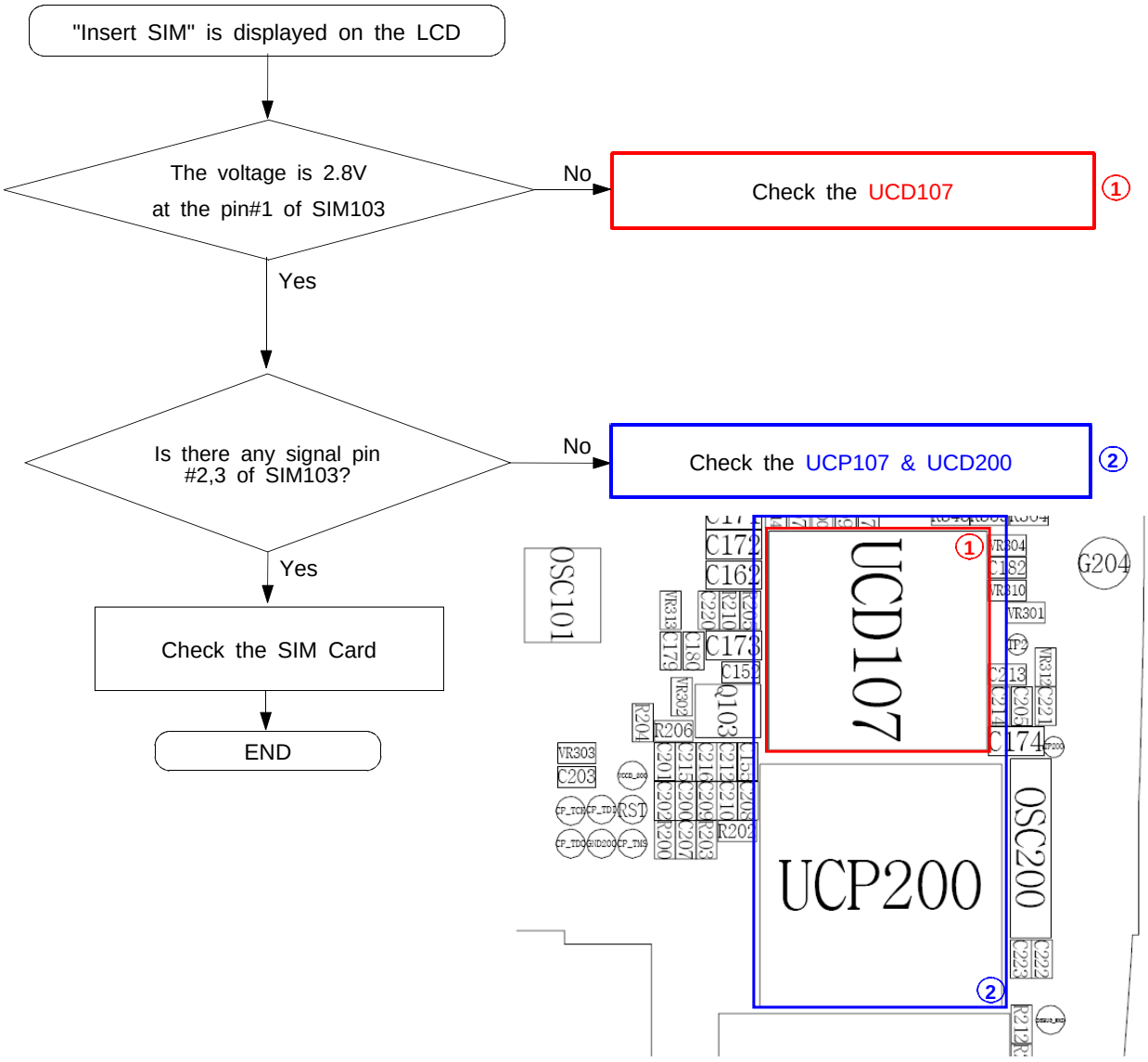
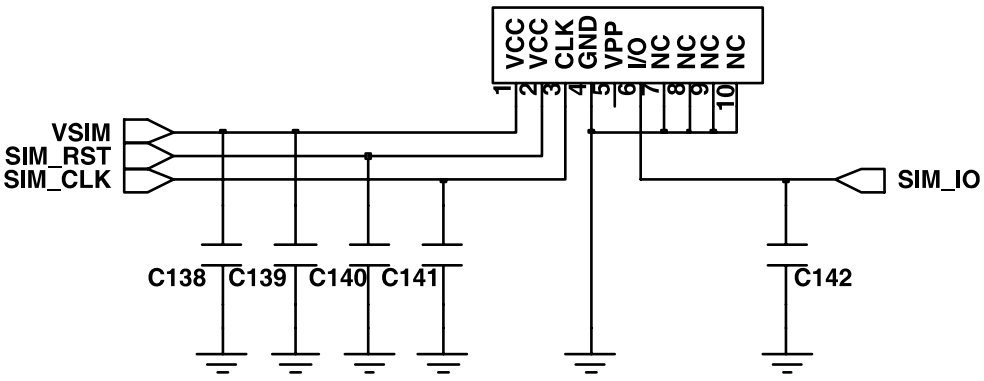
9-1-3. Sim Part



SIM103



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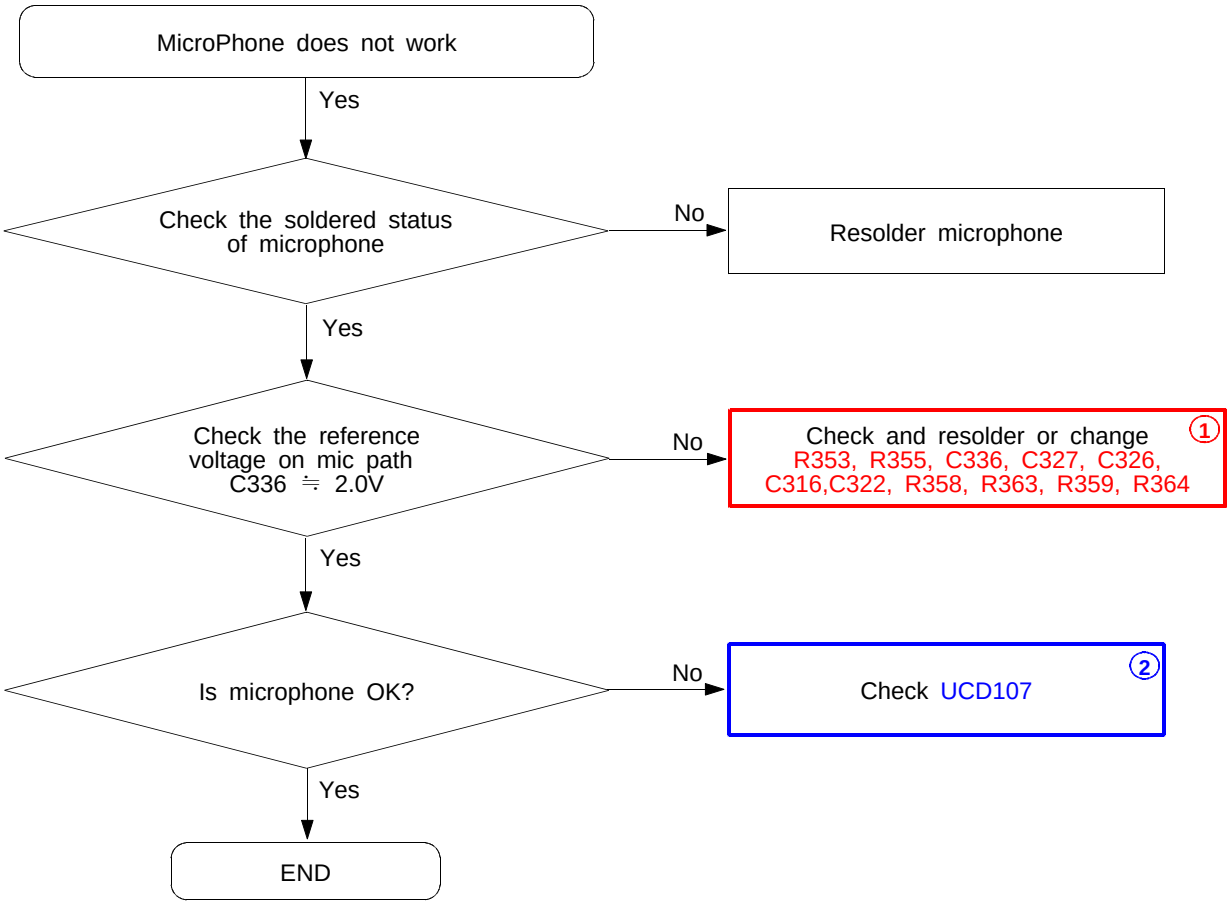
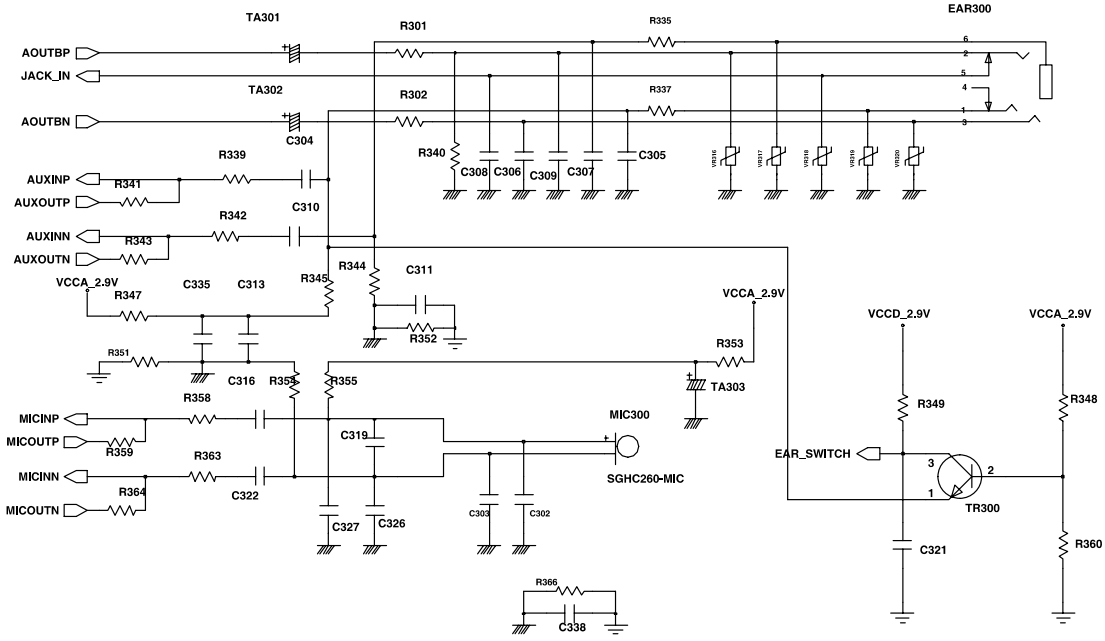
9-1-4.Microphone Part

* Call with Sim before testing.





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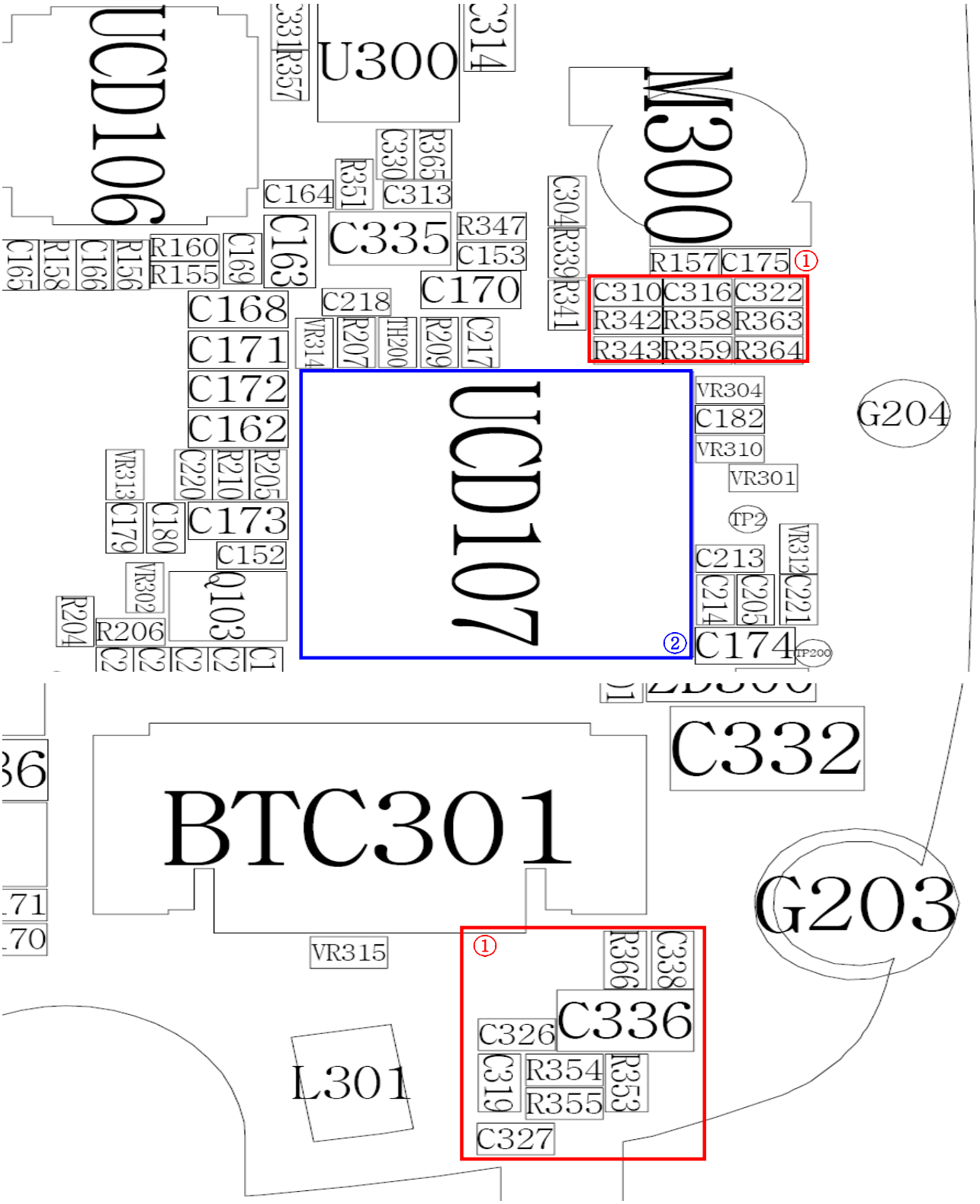

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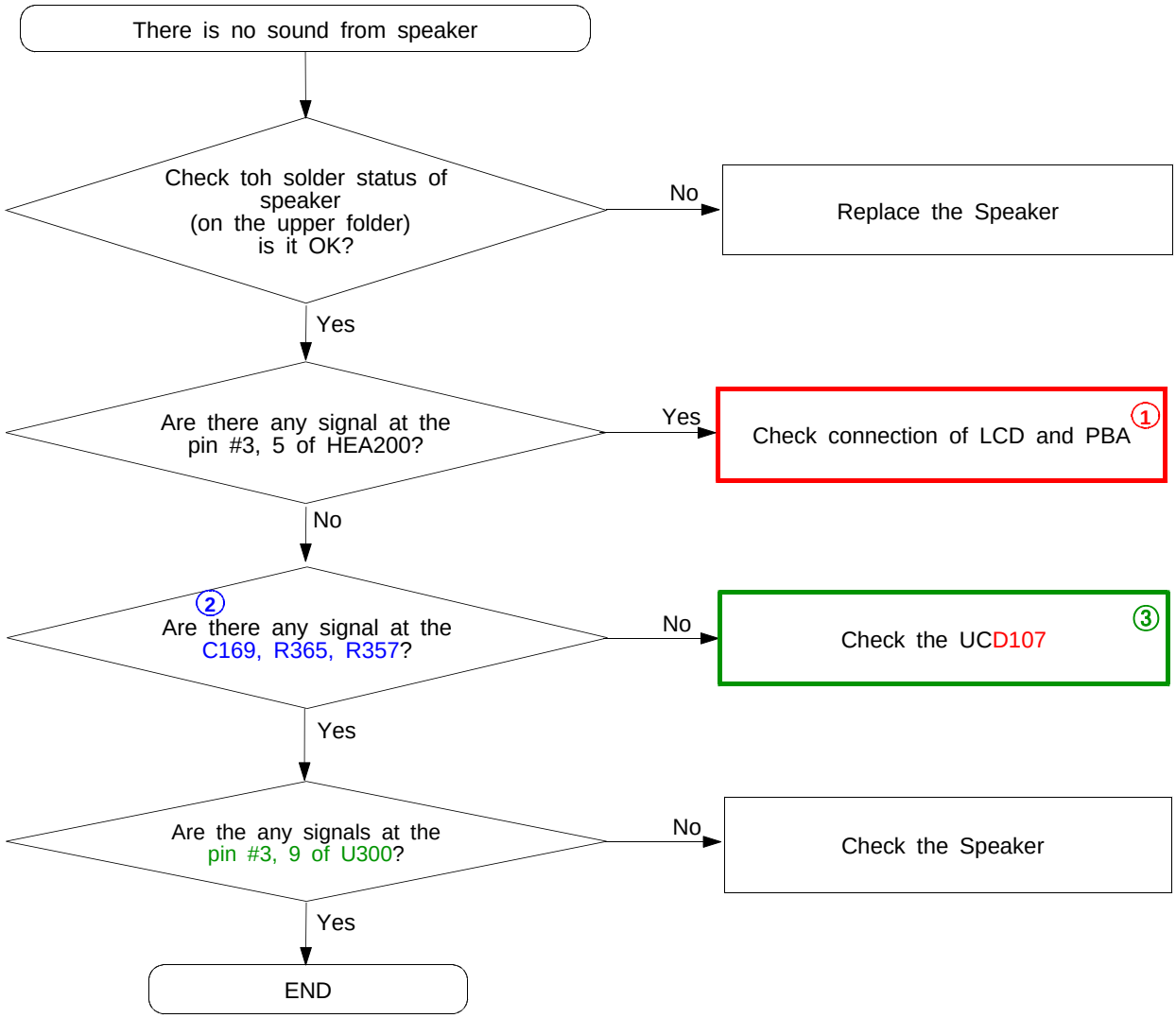
9-1-5. Speaker Part



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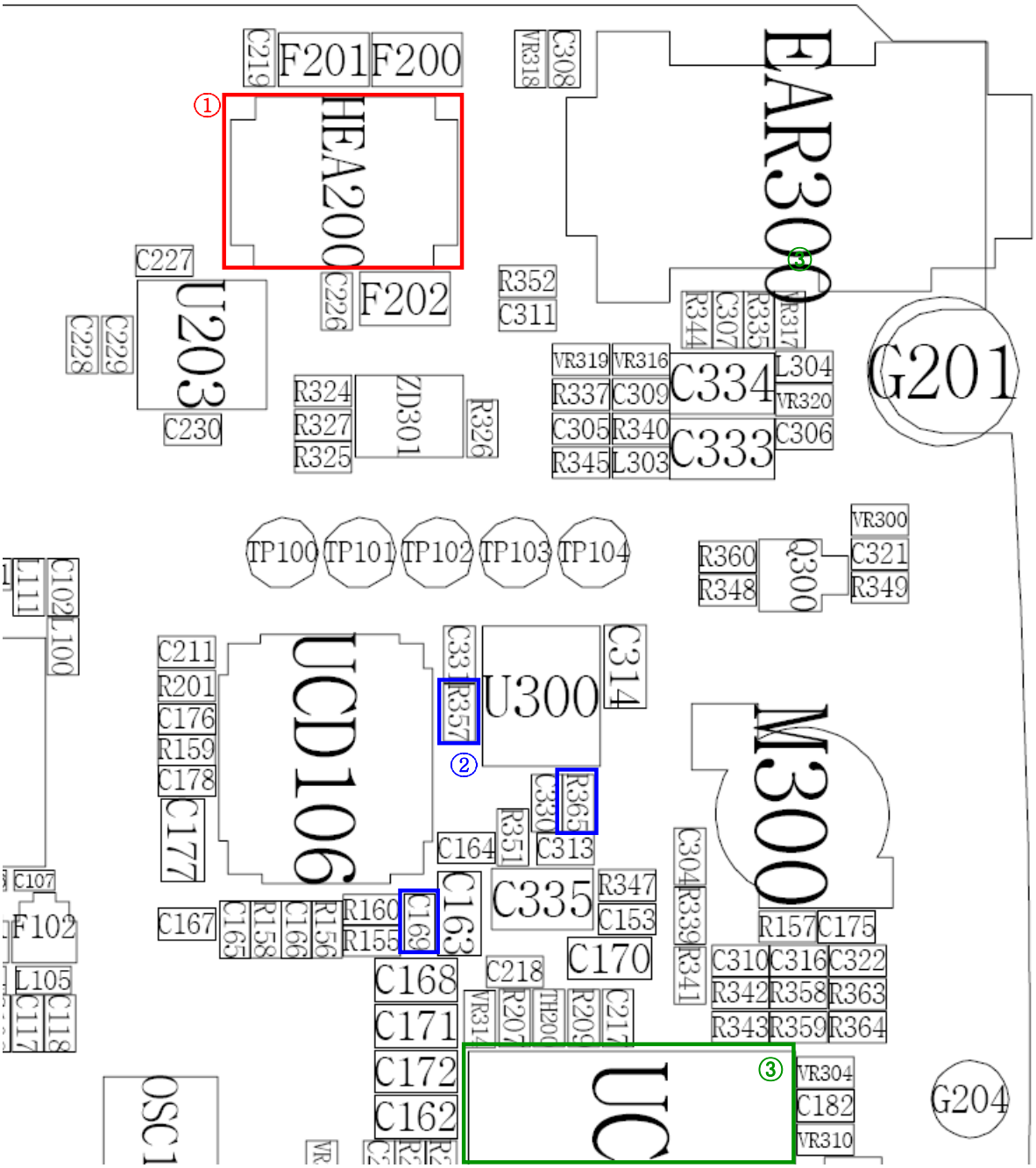

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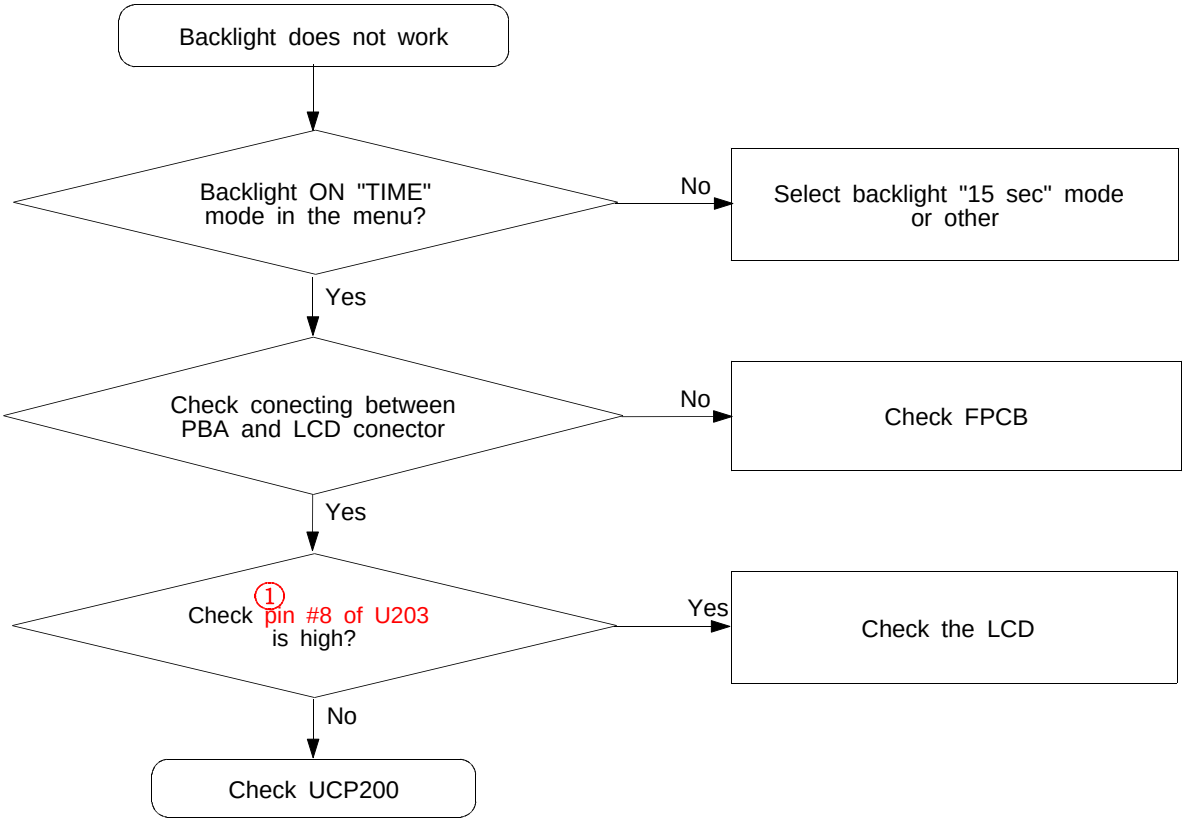
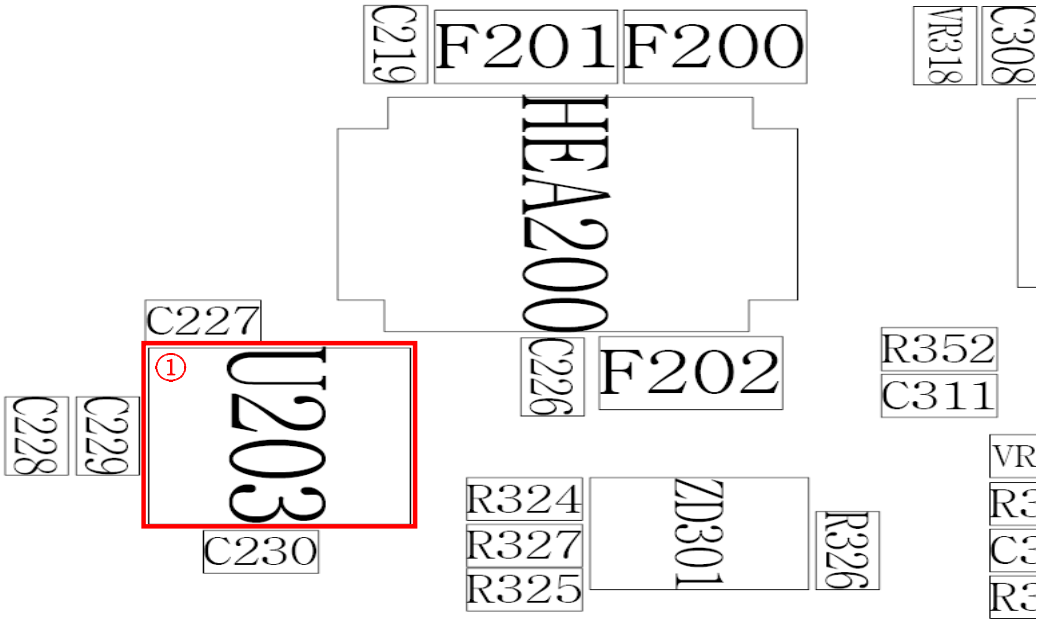
9-1-6. LCD backlight





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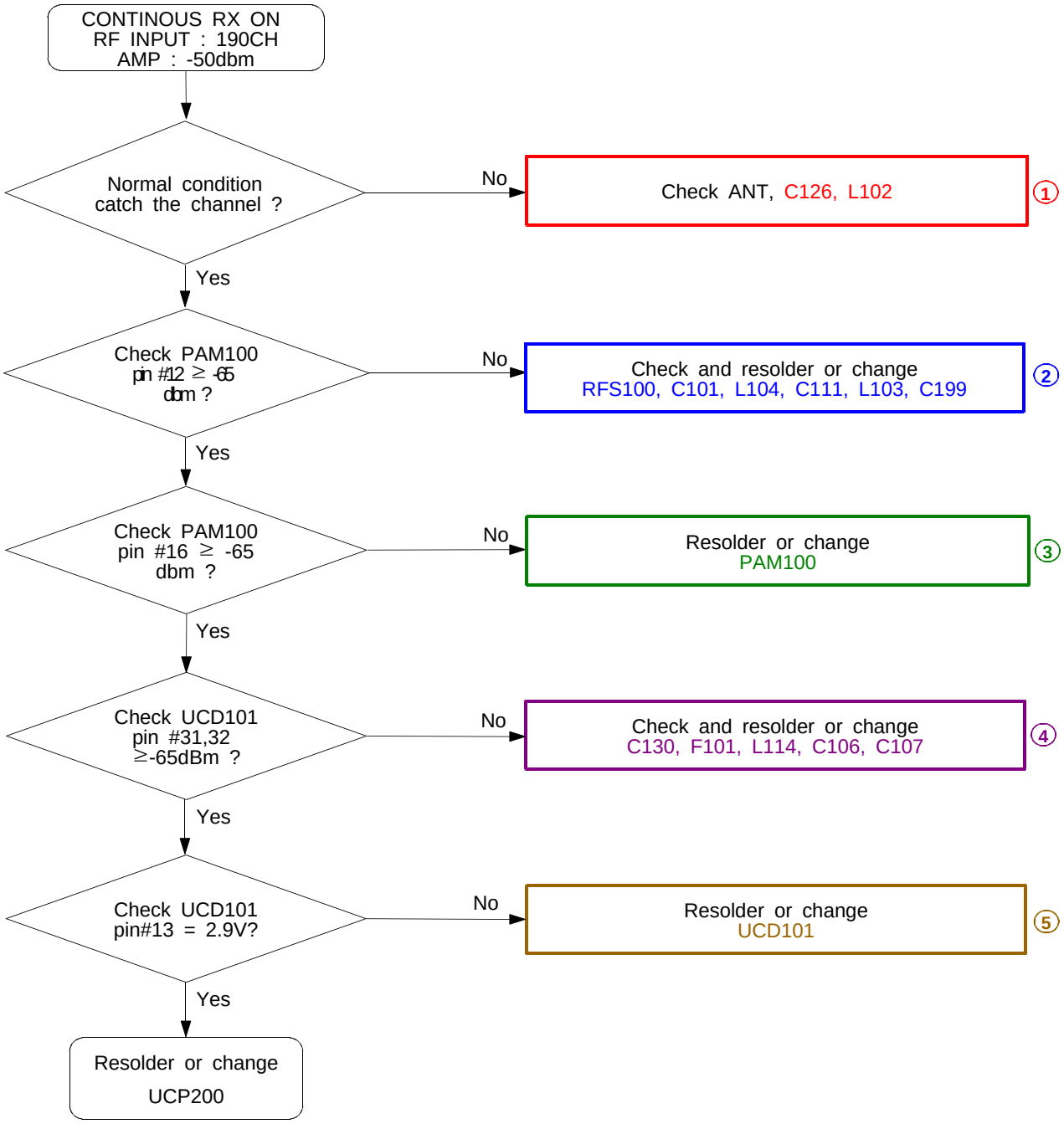
9-2. RF

9-2-1. GSM Rx



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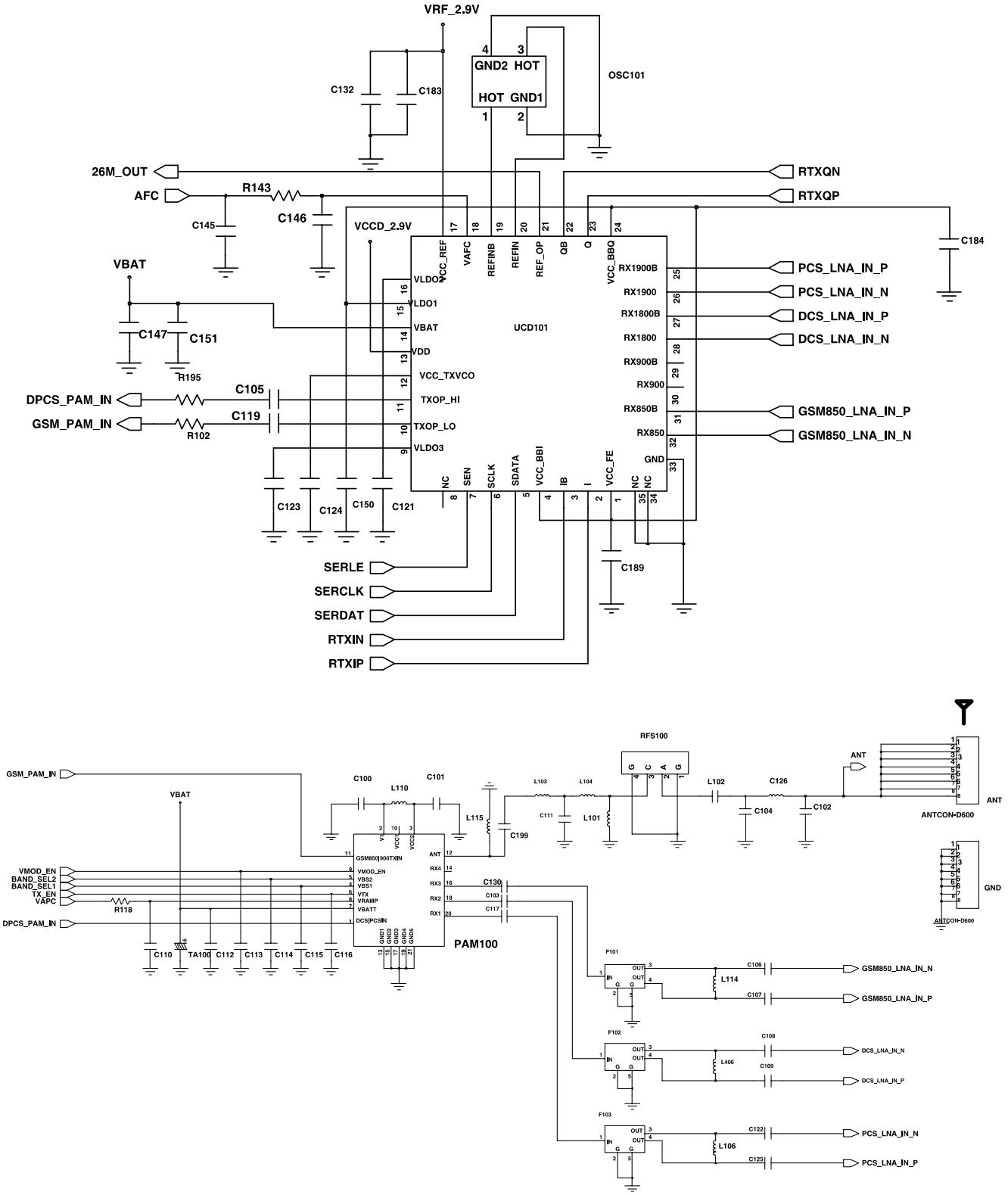

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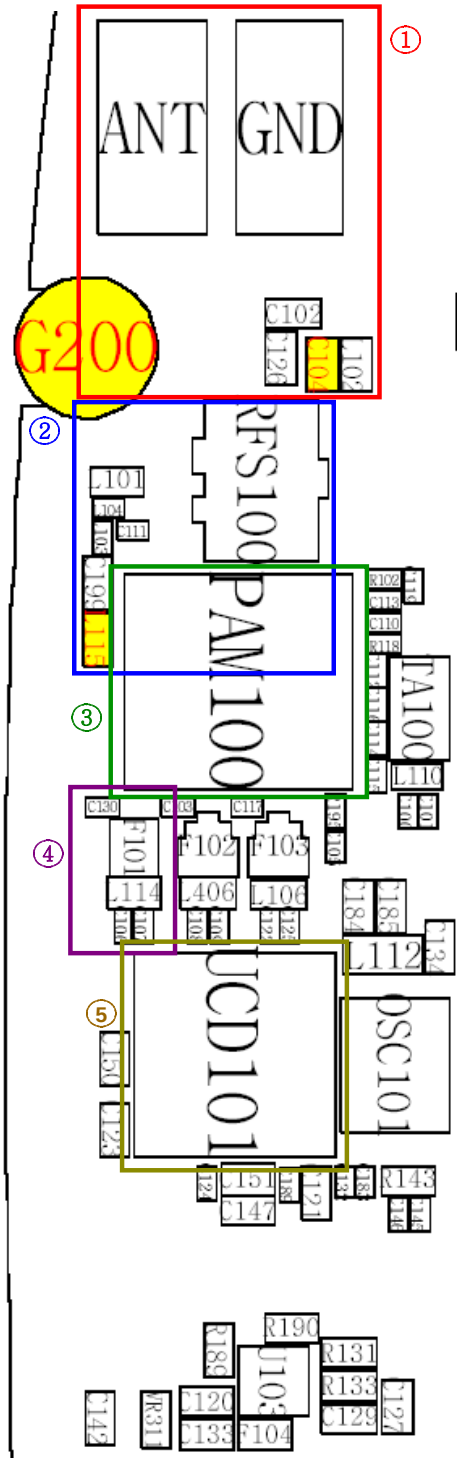
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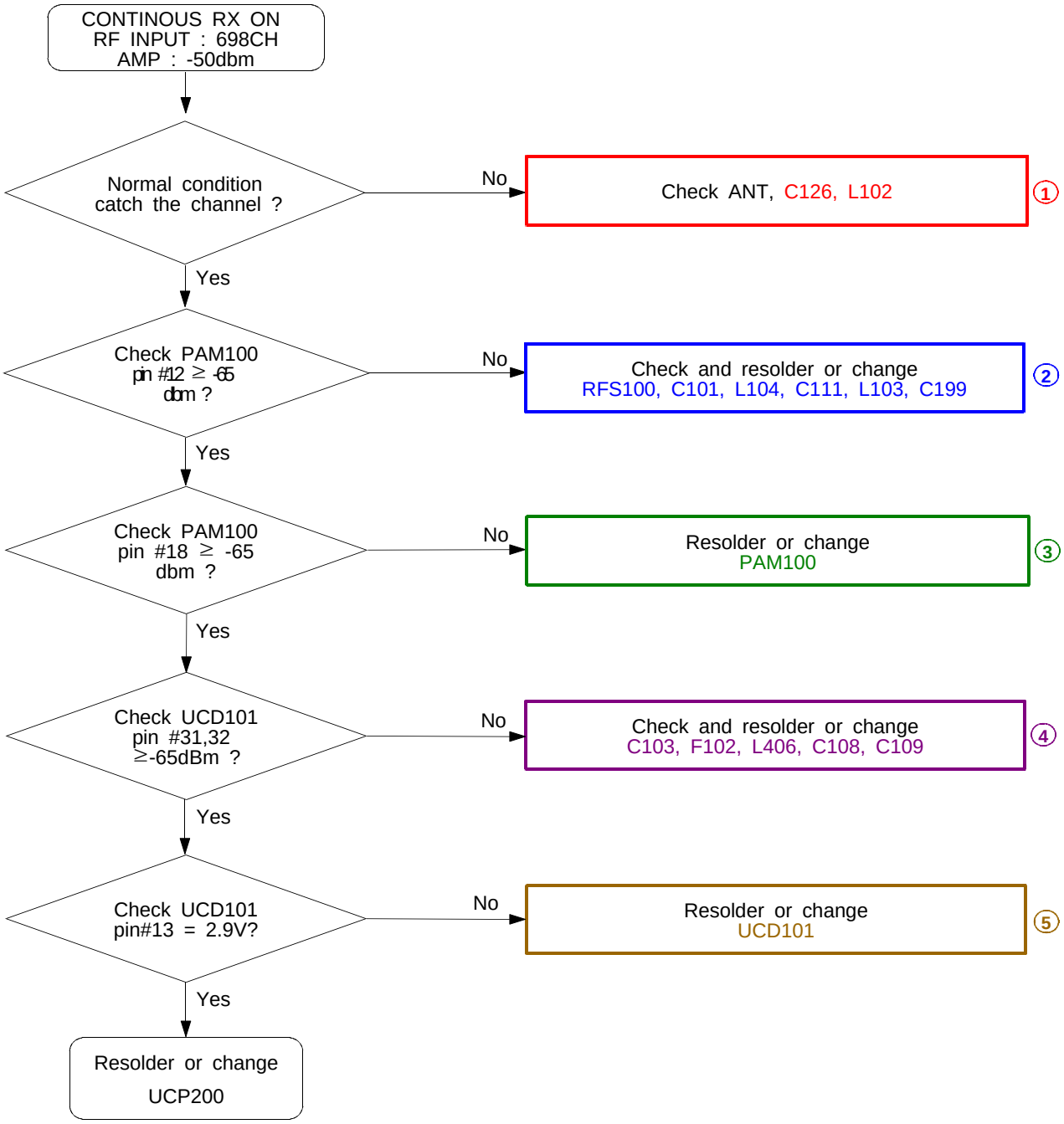
9-2-2. DCS Rx



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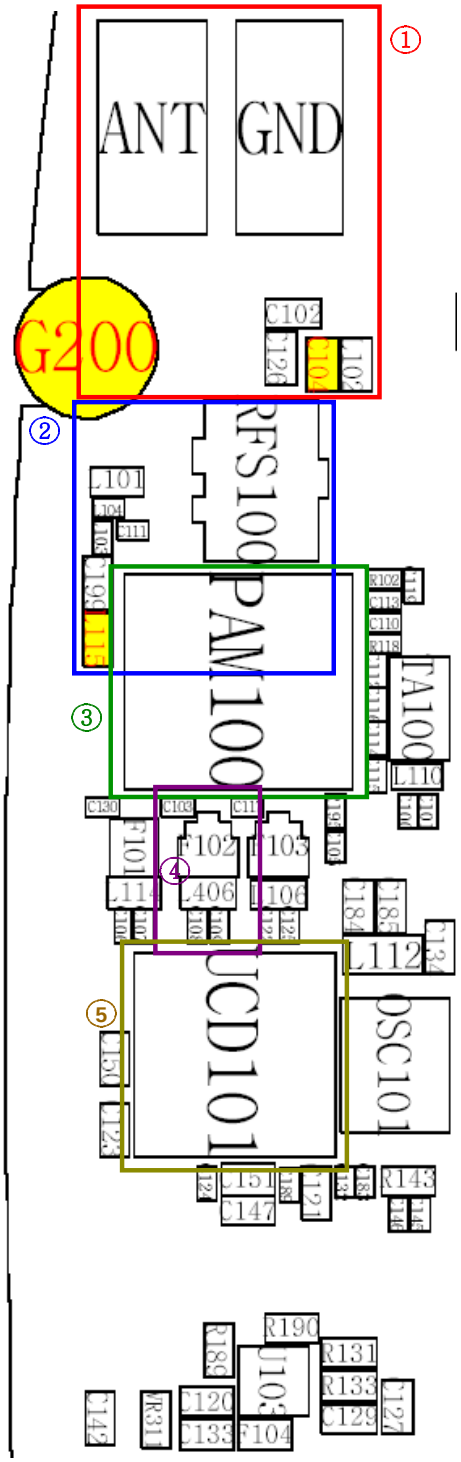

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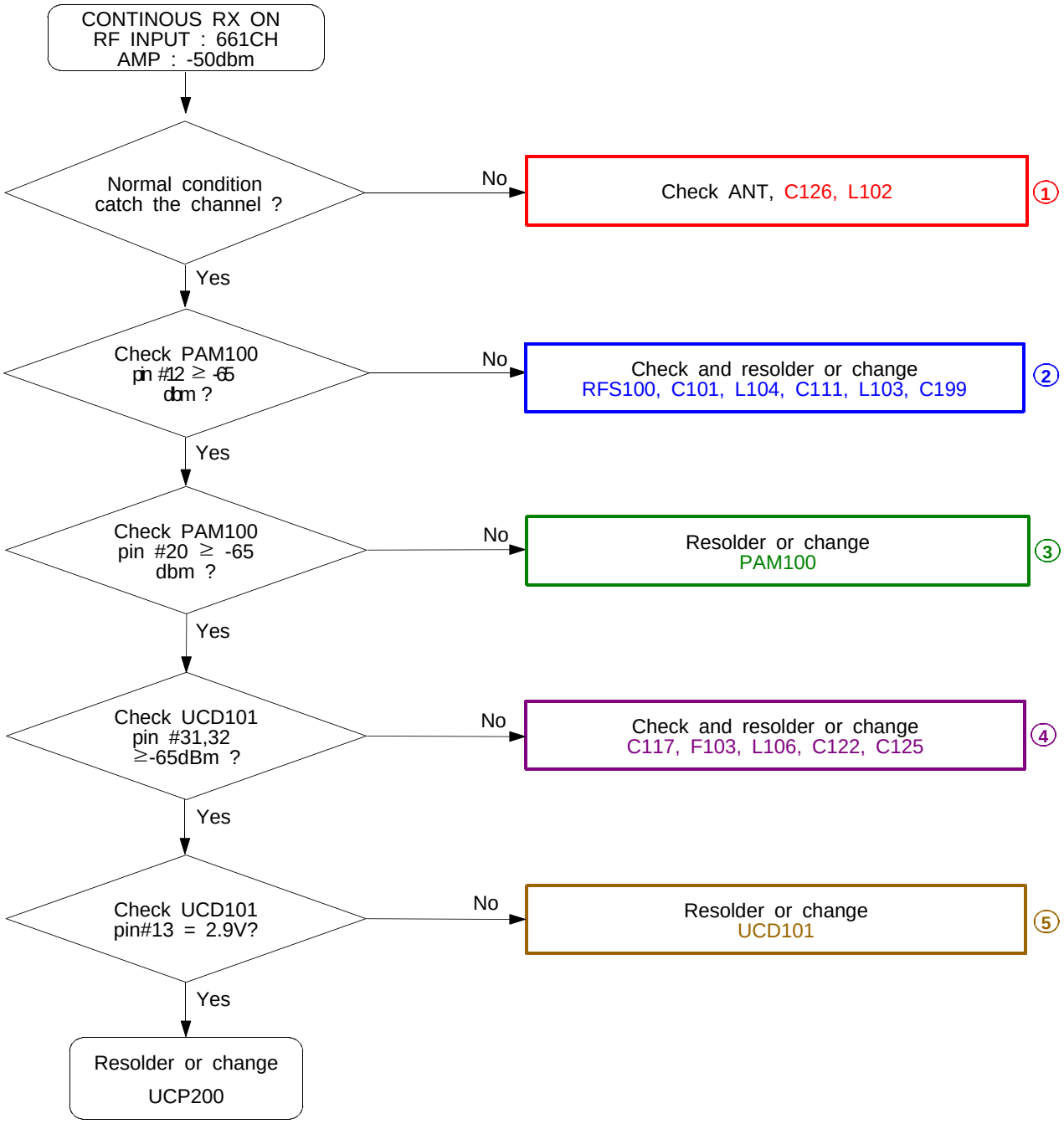

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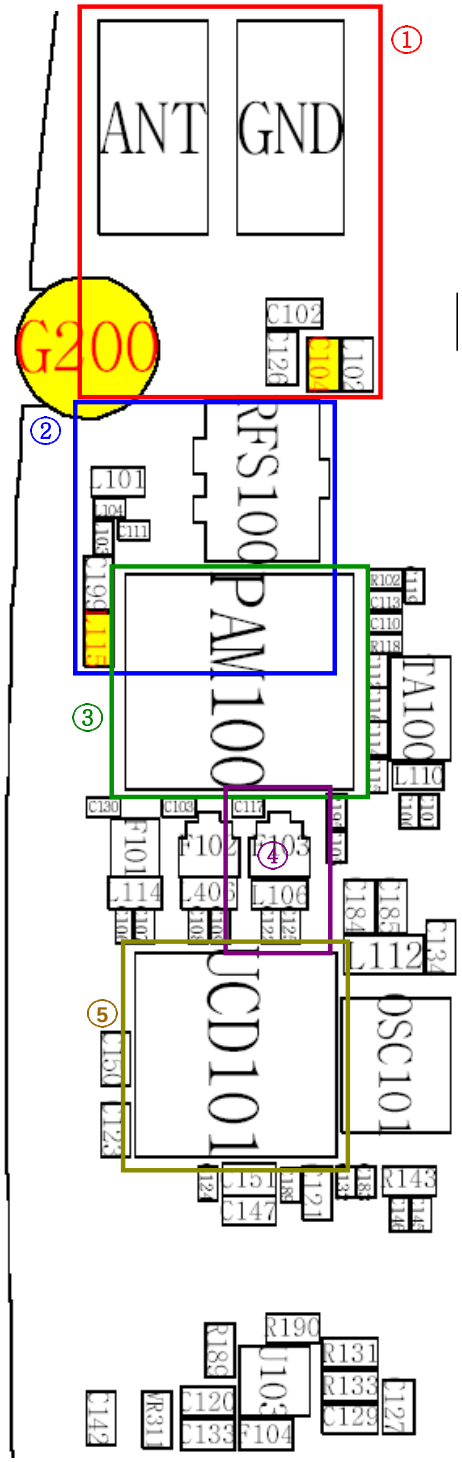

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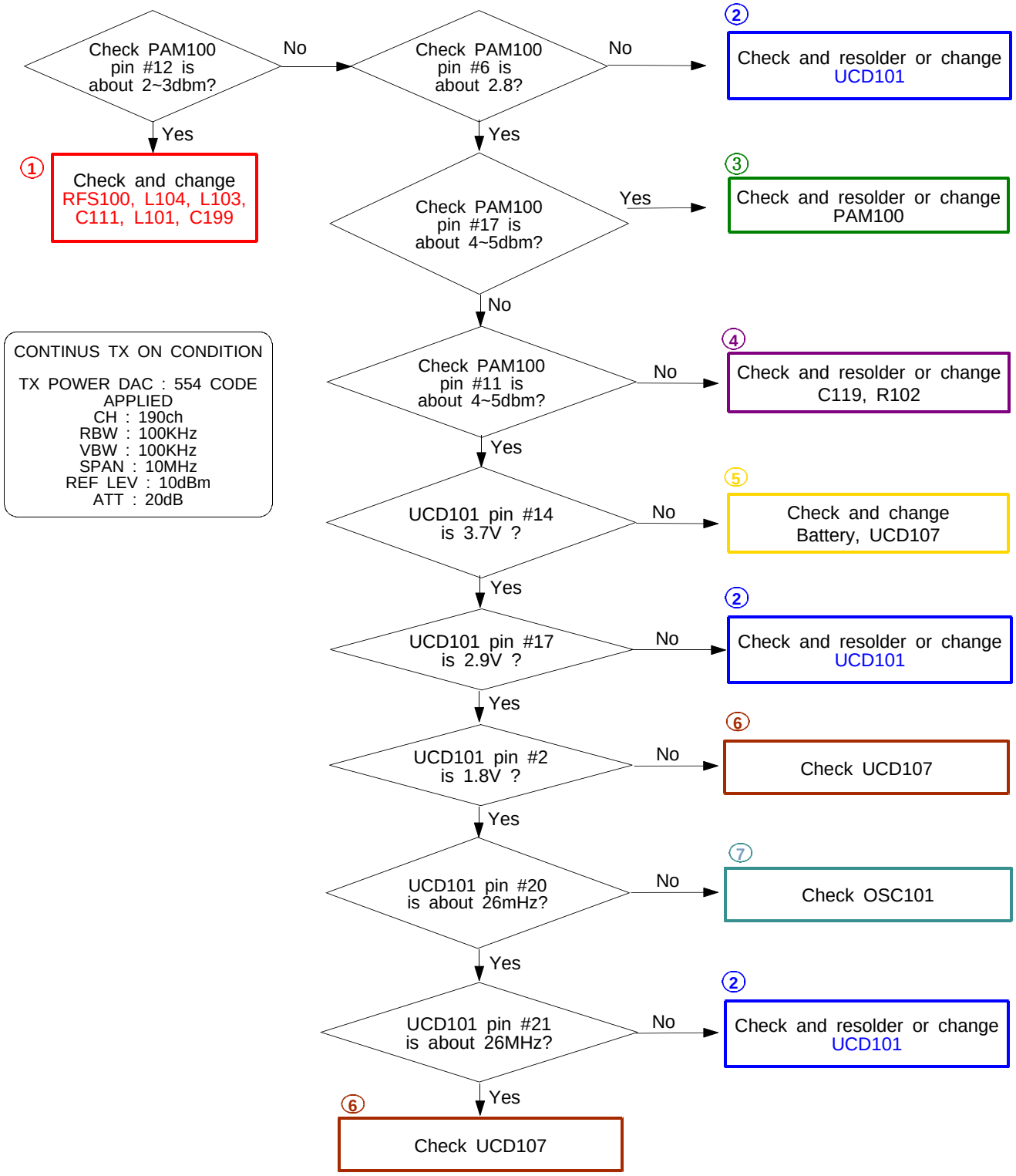

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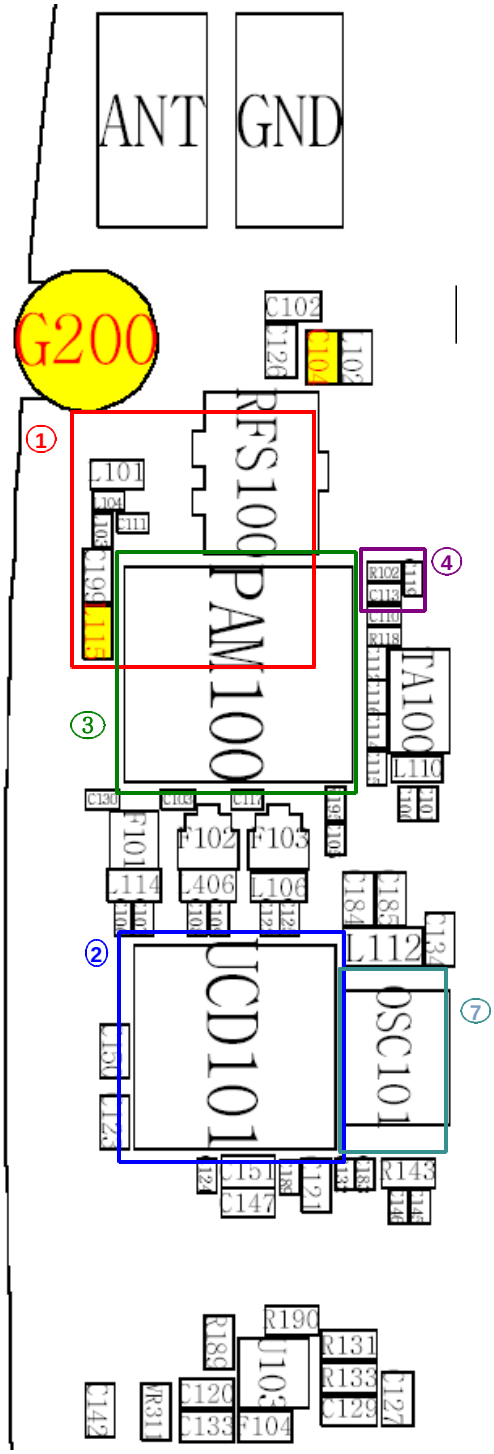

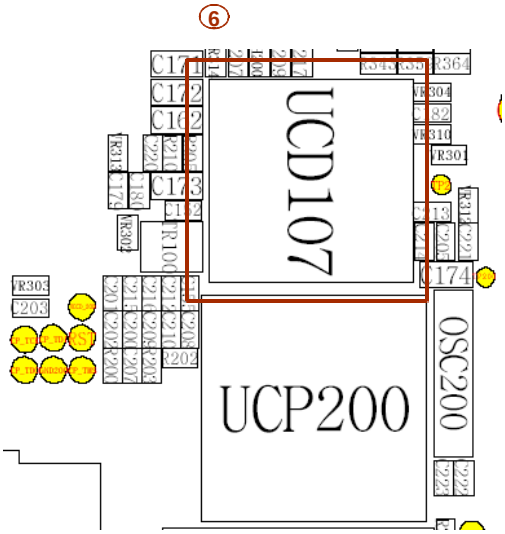

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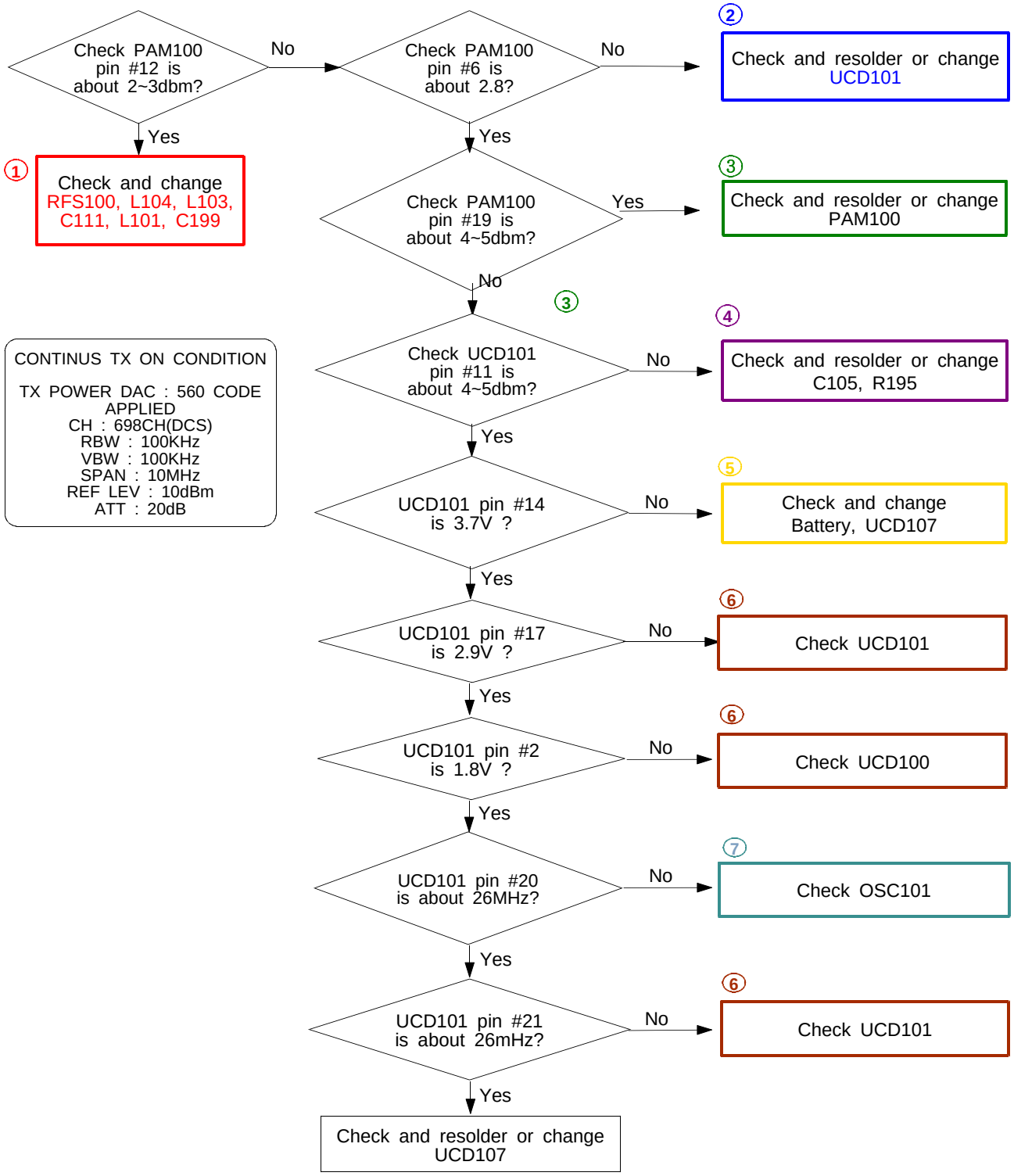

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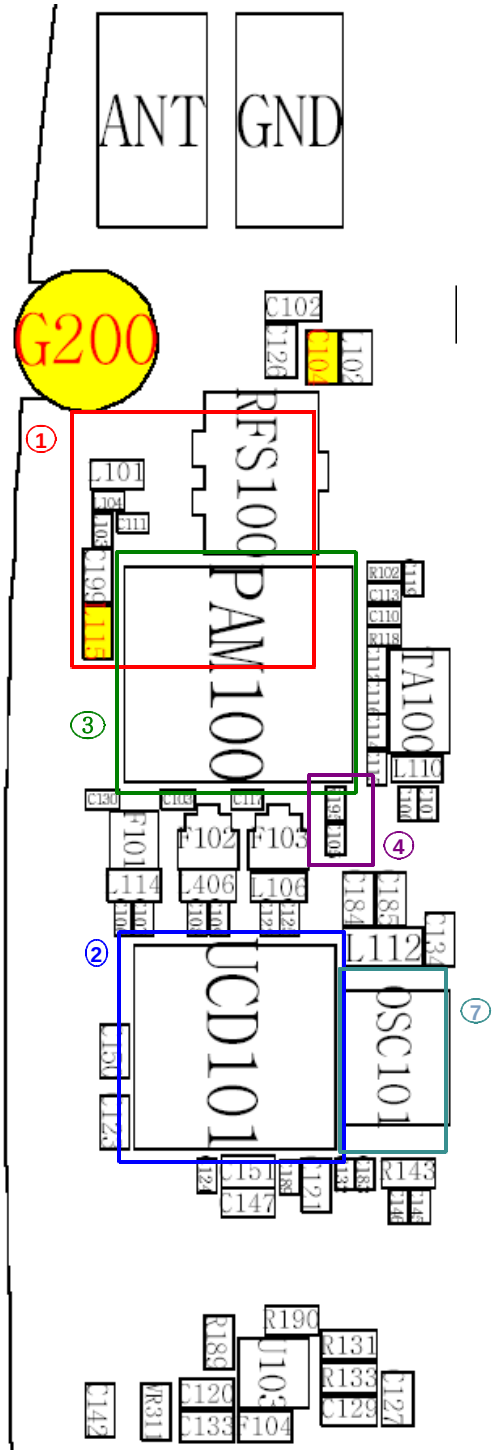

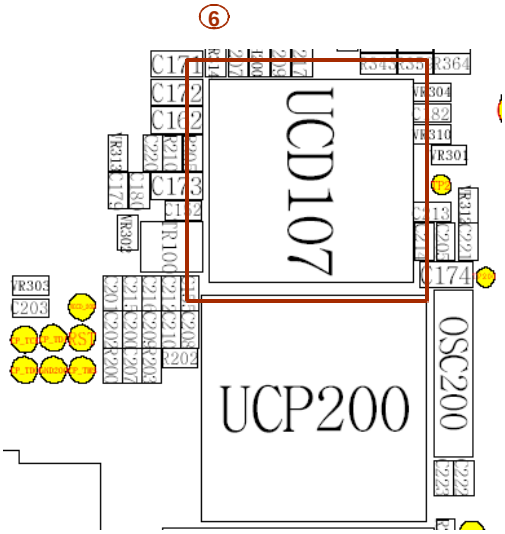

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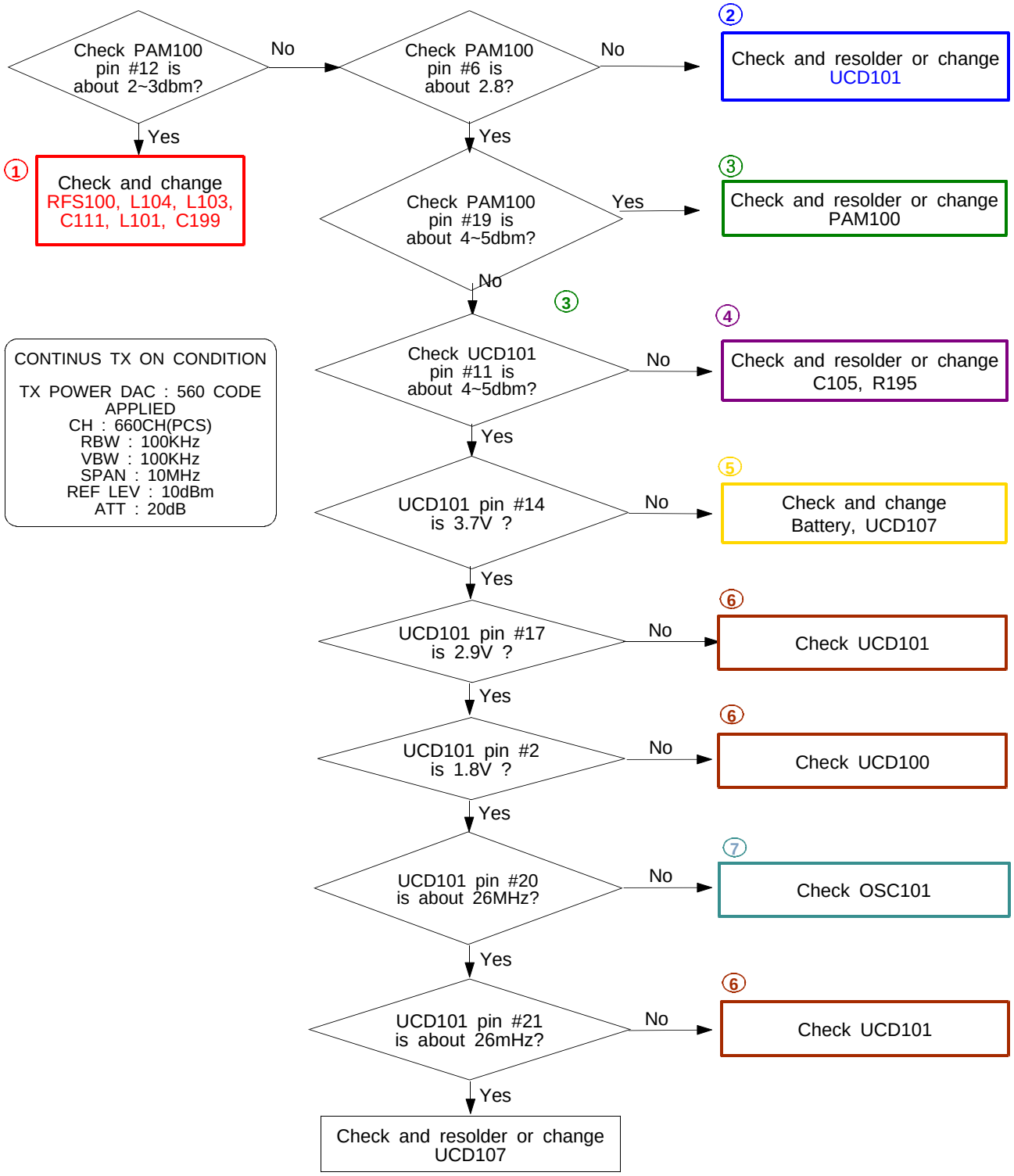
9-2-6. PCS Tx



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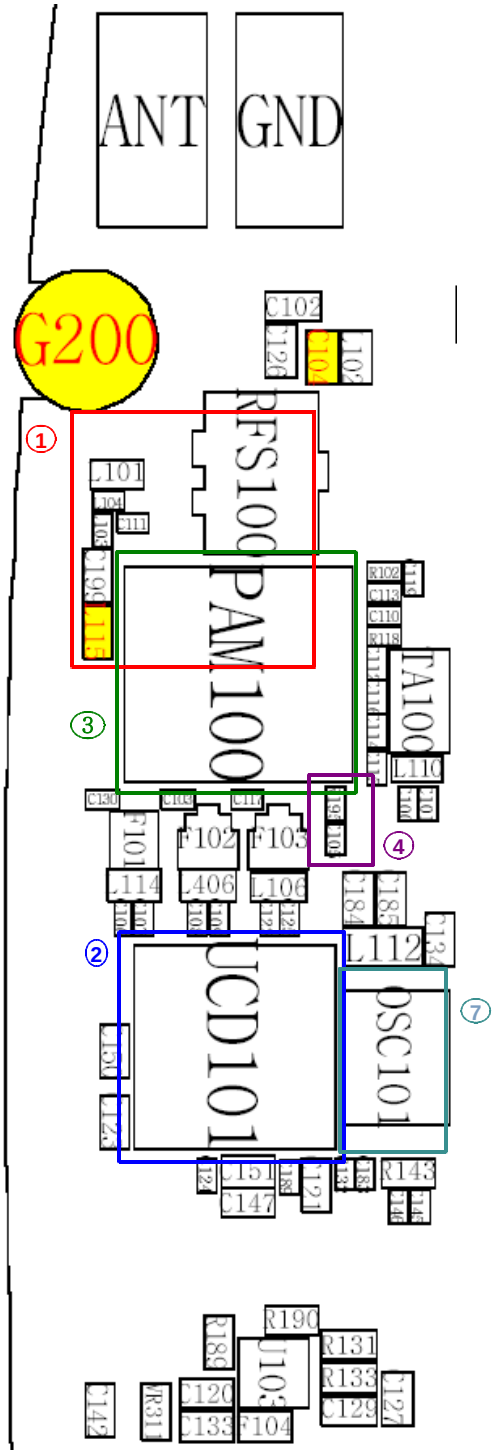

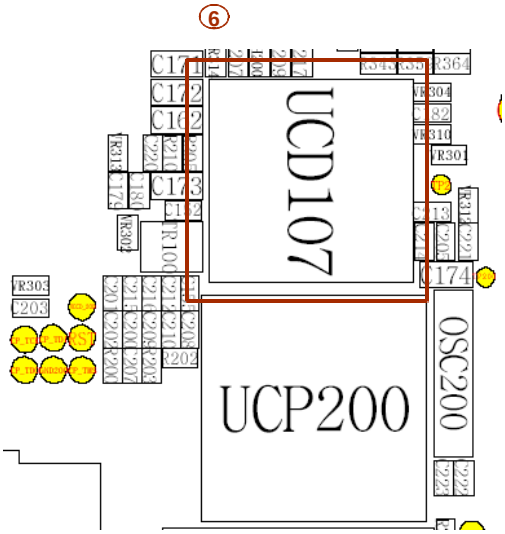

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10. Reference data

Reference Abbreviate

- **AAC**: Advanced Audio Coding.
- **AVC** : Advanced Video Coding.
- **BER** : Bit Error Rate
- **BPSK**: Binary Phase Shift Keying
- **CA** : Conditional Access
- **CDM** : Code Division Multiplexing
- **C/I** : Carrier to Interference
- **DMB** : Digital Multimedia Broadcasting
- **EN** : European Standard
- **ES** : Elementary Stream
- **ETSI**: European Telecommunications Standards Institute
- **MPEG**: Moving Picture Experts Group
- **PN** : Pseudo-random Noise
- **PS** : Pilot Symbol
- **QPSK**: Quadrature Phase Shift Keying
- **RS** : Reed-Solomon
- **SI** : Service Information
- **TDM** : Time Division Multiplexing
- **TS** : Transport Stream

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